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SEMICONDUCTOR DEVICE

Abstract

In a semiconductor device, a semiconductor element has a front electrode and a back electrode. The back electrode is connected to a wiring member through a bonding member. Wire pieces are disposed in the bonding member, and bonded to a bonding surface of the wiring member to protrude toward the semiconductor element. The bonding member has, in a plan view, a central region that overlaps with a central portion of the semiconductor element including an element center, and an outer peripheral region that includes a portion overlapping with an outer peripheral portion of the semiconductor element surrounding the central portion and surrounds the central region. At least four wire pieces are disposed in the outer peripheral region at positions corresponding to at least four respective corners of the semiconductor element. At least one wire piece is disposed to extend toward the element center in the plan view.

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Background/Summary

CROSS REFERENCE TO RELATED APPLICATIONS [0001] The present application is a divisional application of U.S. Utility application Ser. No. 17/708,525 filed on Mar. 30, 2022, which is a continuation application of International Patent Application No. PCT/JP2020/036372 filed on Sep. 25, 2020, which designated the U.S. and claims the benefit of priority from Japanese Patent Application No. 2019-184066 filed on Oct. 4, 2019 and Japanese Patent Application No. 2020-158041 filed on Sep. 22, 2020. The entire disclosures of all of the above applications are incorporated herein by reference.

TECHNICAL FIELD

[0002] The present disclosure relates to a semiconductor device.

BACKGROUND

[0003] JP 5510623 B1 describes to use a Ni ball to ensure a solder thickness. The contents of JP 5510623 B1 are incorporated by reference as a description of technical elements of the present disclosure.

SUMMARY

[0004] The present disclosure describes a semiconductor device including a semiconductor element having main electrodes on both sides, a bonding member, a wiring member, and a plurality of wire pieces. The bonding member is disposed between a first facing surface and a second surface, each of which are provided by the semiconductor element or the wiring member, to form a bonding part. The wiring member is electrically connected to at least one of the main electrodes through the bonding member. The wire pieces are disposed in the bonding member, and fixed to the first facing surface to protrude from the first facing surface toward the second facing surface.

Description

BRIEF DESCRIPTION OF DRAWINGS

[0005] Objects, features and advantages of the present disclosure will become more apparent from the following detailed description made with reference to the accompanying drawings, in which:

[0006] FIG. 1 is a circuit diagram of a power conversion device to which a semiconductor device according to a first embodiment is applied;

[0007] FIG. 2 is a plan view of a semiconductor device;

[0008] FIG. 3 is a sectional view taken along a line III-III of FIG. 2;

[0009] FIG. **4** is a sectional view taken along a line IV-IV of FIG. **2**;
[0010] FIG. **5** is a plan view in which a sealing resin body is omitted;
[0011] FIG. **6** is a plan view in which a heatsink on an emitter electrode side is omitted;
[0012] FIG. **7** is a plan view illustrating a positional relationship between a semiconductor element and wire pieces;
[0013] FIG. **8** is a perspective view illustrating an arrangement of wire pieces;
[0014] FIG. **9** is a sectional view taken along a line IX-IX of FIG. **7**;
[0015] FIG. **10** is a perspective view illustrating the warpage of the semiconductor element and the effect of the wire pieces;
[0016] FIG. **11** is a plan view illustrating a height of a wire piece in the semiconductor device according to a second embodiment;
[0017] FIG. **12** is a plan view illustrating a positional relationship between a semiconductor element and wire pieces in a semiconductor device according to a third embodiment;
[0018] FIG. **13** is a sectional view taken along a line XIII-XIII of FIG. **12**;
[0019] FIG. **14** is a sectional view when the semiconductor element is disposed in an inclined manner;
[0020] FIG. **15** is a plan view illustrating an arrangement of wire pieces in a semiconductor device according to a fourth embodiment;
[0021] FIG. **16** is a plan view illustrating a modification;
[0022] FIG. **17** is a plan view illustrating a positional relationship between a semiconductor element and wire pieces in a semiconductor device according to a fifth embodiment;
[0023] FIG. **18** is a plan view illustrating an arrangement of wire pieces;
[0024] FIG. **19** is a sectional view taken along a line XIX-XIX in FIG. **17**;
[0025] FIG. **20** is a plan view illustrating a modification;
[0026] FIG. **21** is a plan view illustrating a positional relationship between a semiconductor element and wire pieces in a semiconductor device according to a sixth embodiment;
[0027] FIG. **22** is a schematic sectional view illustrating an influence of a positional relationship between the wire pieces in upper and lower portions;
[0028] FIG. **23** is a schematic sectional view illustrating a laminate structure of one arm in a semiconductor device according to a seventh embodiment;
[0029] FIG. **24** is a plan view illustrating an arrangement of wire pieces in each solder;
[0030] FIG. **25** is a view illustrating the difference in a terminal between a semiconductor device according to an eighth embodiment and a comparative example;
[0031] FIG. **26** is a perspective view illustrating an example of a connection structure between a semiconductor element and a heatsink in a semiconductor device according to a ninth embodiment;
[0032] FIG. **27** is a sectional view taken along a line XXVII-XXVII of FIG. **26**;
[0033] FIG. **28** is a perspective view illustrating a wire piece;
[0034] FIG. **29** is a sectional view illustrating another example of the wire piece;
[0035] FIG. **30** is a sectional view illustrating a method for manufacturing the semiconductor device;
[0036] FIG. **31** is a sectional view illustrating the method for manufacturing the semiconductor device;
[0037] FIG. **32** is a sectional view illustrating the method for manufacturing the semiconductor device;
[0038] FIG. **33** is a sectional view illustrating the method for manufacturing the semiconductor device;
[0039] FIG. **34** is a sectional view illustrating the method for manufacturing the semiconductor device;
[0040] FIG. **35** is a sectional view illustrating an example of a semiconductor element without warpage;

[0041] FIG. **36** is a sectional view illustrating an example of a semiconductor element having warped upward;
[0042] FIG. **37** is a sectional view illustrating an example of a semiconductor element having warped downward;
[0043] FIG. **38** is a sectional view illustrating an effect of having flat parts at both ends;
[0044] FIG. **39** is a sectional view illustrating another example of the semiconductor device;
[0045] FIG. **40** is a simulation result illustrating a relationship between a volume of a wire piece and solder deformation in the semiconductor device according to a tenth embodiment;
[0046] FIG. **41** is a view illustrating the structure of the wire piece;
[0047] FIG. **42** is a sectional view for explaining the height of the wire piece between a collector electrode and the heatsink;
[0048] FIG. **43** is a sectional view for explaining the height of the wire piece between the emitter electrode and the terminal;
[0049] FIG. **44** is a sectional view illustrating a method for manufacturing the wire piece;
[0050] FIG. **45** is a sectional view illustrating the method for manufacturing the wire piece;
[0051] FIG. **46** is a sectional view illustrating the method for manufacturing the wire piece;
[0052] FIG. **47** is a sectional view illustrating the method for manufacturing the wire piece; and
[0053] FIG. **48** is a sectional view illustrating the method for manufacturing the wire piece.

DETAILED DESCRIPTION

[0054] It is known to use a Ni ball to ensure a solder thickness in a semiconductor device. However, the application target of the Ni ball is limited. For example, in the case of solder die bonding, the Ni ball melts in no small amount in a solder melting furnace. Hence there is a possibility that the minimum ensured thickness of the solder (bonding member) cannot be ensured. From such a viewpoint or from other viewpoints not mentioned, further improvement is required for the semiconductor device.

[0055] The present disclosure provides a semiconductor device which has high reliability.

[0056] According to an aspect of the present disclosure, a semiconductor device includes a semiconductor element, a bonding member, a wiring member, and a plurality of wire pieces. The semiconductor element has a front surface and a back surface opposite to the front surface in a plate thickness direction of the semiconductor element. The semiconductor element includes, as main electrodes, a front electrode on the front surface and a back electrode on the back surface, and the back electrode has an area larger than an area of the front electrode. The bonding member is disposed between a first facing surface and a second facing surface to form a bonding part. The wiring member is electrically connected to at least one of the main electrodes through the bonding member. The plurality of wire pieces are disposed in the bonding member, and fixed to the first facing surface to protrude from the first facing surface. The wiring member includes a back-side wiring member disposed adjacent to the back surface of the semiconductor element and electrically connected to the back electrode. The bonding member includes a back-side bonding member that forms a bonding part between the back electrode and the back-side wiring member. The back-side bonding member has, in a plan view in the plate thickness direction, a central region that overlaps with a central portion of the semiconductor element including an element center, and an outer peripheral region that includes a portion overlapping with an outer peripheral portion of the semiconductor element surrounding the central portion and surrounds the central region. The plurality of wire pieces include at least four wire pieces disposed in the outer peripheral region of the back-side bonding member at positions corresponding to at least four respective corners of the semiconductor element. The plurality of wire pieces include at least one wire piece disposed to extend toward the element center in the plan view.

[0057] According to the semiconductor device described above, the wire pieces are fixed to the first facing surface. The thickness of the bonding member can be ensured by the wire pieces protruding from the first facing surface. Even when the semiconductor element having the main electrodes on

both surfaces has warped, the thickness of the bonding member can be ensured by the wire pieces provided in the outer peripheral region. The wire piece extending toward the element center hardly obstructs the flow when the solder wets and spreads. As described above, a highly reliable semiconductor device can be provided.

[0058] Hereinafter, a plurality of embodiments will be described with reference to the drawings. In the plurality of embodiments, functionally and/or structurally corresponding and/or associated portions may be provided with the same reference numerals. For the corresponding and/or associated portions, reference may be made to descriptions of other embodiments.

First Embodiment

[0059] First, an example of a power conversion device to which a semiconductor device is applied will be described with reference to FIG. 1.

<Power Conversion Device>

[0060] A power conversion device **1** illustrated in FIG. 1 is mounted on, for example, an electric vehicle or a hybrid vehicle. The power conversion device **1** performs power conversion between a direct current (DC) power supply **2** and the motor generator **3**. The power conversion device **1** constitutes a drive system of a vehicle together with the DC power supply **2** and the motor generator **3**.

[0061] The DC power supply **2** is a chargeable/dischargeable secondary battery such as a lithium-ion battery or a nickel-hydrogen battery. The motor generator **3** is a three-phase alternating current (AC) rotating electrical machine. The motor generator **3** functions as a traveling drive source of the vehicle, that is, an electric motor. The motor generator **3** functions as a generator during regeneration.

[0062] The power conversion device **1** includes a smoothing capacitor **4** and an inverter **5** that is a power converter. A positive electrode side terminal of the smoothing capacitor **4** is connected to a positive electrode that is an electrode on a high potential side of the DC power supply **2**, and a negative electrode side terminal is connected to a negative electrode that is an electrode on a low potential side of the DC power supply **2**. The inverter **5** converts the input DC power into a three-phase AC of a predetermined frequency and outputs the three-phase AC to the motor generator **3**. The inverter **5** converts AC power generated by the motor generator **3** into DC power. The inverter **5** is a DC to AC converter.

[0063] The inverter **5** includes upper and lower arm circuits **6** for three phases. The upper and lower arm circuit **6** may be referred to as a leg. The upper and lower arm circuit **6** of each phase is formed by connecting two arms **6H**, **6L** in series between a high-potential power supply line **7**, which is a power supply line on the positive electrode side, and a low-potential power supply line **8**, which is a power supply line on the negative electrode side. In the upper and lower arm circuit **6** of each phase, a connection point between the upper arm **6H** and the lower arm **6L** is connected to an output line **9** to the motor generator **3**.

[0064] In the present embodiment, an n-channel insulated-gate bipolar transistor **6i** (hereinafter referred to as an IGBT **6i**) is adopted as a switching element constituting each arm. A freewheeling diode (FWD) **6d**, which is a reflux diode, is connected in anti-parallel to each IGBT **6i**. The upper and lower arm circuit **6** for one phase includes two IGBTs **6i**. In the upper arm **6H**, the collector electrode of the IGBT **6i** is connected to the high-potential power supply line **7**. In the lower arm **6L**, the emitter electrode of the IGBT **6i** is connected to the low-potential power supply line **8**. The emitter electrode of the IGBT **6i** in the upper arm **6H** and the collector electrode of the IGBT **6i** in the lower arm **6L** are connected to each other.

[0065] In addition to the smoothing capacitor **4** and the inverter **5** described above, the power conversion device **1** may include a converter that is a power converter different from the inverter **5**, a drive circuit of a switching element constituting each of the inverter **5** and the converter, a filter capacitor, and the like. The converter is a DC-DC converter that converts a DC voltage into a DC voltage having a different value. The converter is provided between the DC power supply **2** and the

smoothing capacitor **4**. The filter capacitor is connected in parallel to the DC power supply **2**. The filter capacitor removes, for example, power supply noise from the DC power supply **2**.

<Semiconductor Device>

[0066] Next, an example of the semiconductor device will be described with reference to FIGS. **2** to **6**. FIGS. **3** and **4** are sectional views taken along lines III-III and IV-IV in FIG. **2**. FIG. **5** is a view in which a sealing resin body is omitted from FIG. **2**. FIG. **6** is a diagram in which a heatsink on the emitter electrode side is omitted from FIG. **5**. “H” indicating the upper arm **6H** side and “L” indicating the lower arm **6L** side are added to the end of the reference numerals of some of the elements constituting the semiconductor device. For the sake of convenience, reference numerals that are common between the upper arm **6H** and the lower arm **6L** are given to some others of the elements.

[0067] Hereinafter, a plate thickness direction of a semiconductor element is referred to as a Z-direction, one direction orthogonal to the Z-direction, specifically, an arrangement direction of two semiconductor elements, is referred to as an X-direction. Further, a direction orthogonal to both the Z-direction and the X-direction is indicated as a Y-direction. Unless otherwise specified, a shape in a plan view from the Z-direction, in other words, a shape along the XY plane defined by the X-direction and the Y-direction, is a planar shape. The plan view from the Z-direction is simply referred to as a plan view.

[0068] As illustrated in FIGS. **2** to **6**, a semiconductor device **10** includes a sealing resin body **20**, a semiconductor element **30**, a heatsink **40**, a heatsink **50**, a terminal **55**, couplings **60** to **62**, main terminals **70** to **72**, and a signal terminal **75**. The semiconductor device **10** constitutes the upper and lower arm circuit **6** for one phase described above.

[0069] The sealing resin body **20** seals a part of each of other elements constituting the semiconductor device **10**. The remaining portions of the other elements are exposed to the outside of the sealing resin body **20**. The sealing resin body **20** is made of, for example, epoxy resin. The sealing resin body **20** is molded by, for example, a transfer molding method. As illustrated in FIGS. **2** to **4**, the sealing resin body **20** has a substantially rectangular planar shape. The sealing resin body **20** has a front surface **20a** and a back surface **20b** opposite to the front surface **20a** in the Z-direction. The front surface **20a** and the back surface **20b** are, for example, flat surfaces.

[0070] The semiconductor element **30** is formed by forming an element on a semiconductor substrate made of silicon (Si), a wide-bandgap semiconductor having a wider bandgap than silicon, or the like. Examples of the wide-bandgap semiconductor include silicon carbide (SiC), gallium nitride (GaN), gallium oxide (Ga.sub.2O.sub.3), and diamond. The semiconductor element **30** may be referred to as a semiconductor chip.

[0071] The element has a vertical structure such that a main current flows in the Z-direction. As a vertical element, an IGBT, a metal-oxide-semiconductor field-effect transistor (MOSFET), a diode, or the like can be adopted. In the present embodiment, the IGBT **6i** and the FWD **6d** constituting one arm are formed as the vertical elements. The vertical element is a reverse conducting (RC)-IGBT. The semiconductor element **30** has a gate electrode (not illustrated). The gate electrode has, for example, a trench structure. The semiconductor element **30** has main electrodes of the element on both surfaces in the plate thickness direction thereof, that is, the Z-direction. Specifically, as the main electrodes, an emitter electrode **31** is provided on the front surface side, and a collector electrode **32** is provided on the back surface side. The emitter electrode **31** also serves as the anode electrode of the FWD **6d**. The collector electrode **32** also serves as the cathode electrode of the FWD **6d**. The emitter electrode **31** corresponds to a front electrode, and the collector electrode **32** corresponds to a back electrode.

[0072] The semiconductor element **30** has a substantially rectangular planar shape. As illustrated in FIG. **6**, the semiconductor element **30** has a pad **33** formed at a position different from the emitter electrode **31** on the front surface. The emitter electrode **31** and the pad **33** are exposed from a protective film (not illustrated) on the front surface of the semiconductor substrate. The emitter

electrode **31** is formed on a portion of the front surface of the semiconductor element **30**. The collector electrode **32** is formed on substantially the entire back surface. In a plan view, the collector electrode **32** is larger in area than the emitter electrode **31**.

[0073] The pad **33** is an electrode for a signal. The pad **33** is electrically separated from the emitter electrode **31**. The pad **33** is formed at an end opposite to the formation region of the emitter electrode **31** in the Y-direction. The pad **33** includes a gate pad **33g** for the gate electrode. In the present embodiment, the semiconductor element **30** has five pads **33**. Specifically, the semiconductor element **30** has the gate pad **33g** described above, a pad for a Kelvin emitter that detects the potential of the emitter electrode **31**, a pad for current sensing, a pad for an anode potential of a temperature sensor (thermosensitive diode) that detects the temperature of the semiconductor element **30**, and a pad for a cathode potential of the temperature sensor. The five pads **33** are collectively formed on one end side in the Y-direction and are formed side by side in the X-direction in the semiconductor element **30** having a substantially rectangular planar shape.

[0074] The semiconductor device **10** includes two semiconductor elements **30**. Specifically, a semiconductor element **30H** constituting the upper arm **6H** and a semiconductor element **30L** constituting the lower arm **6L** are provided. The semiconductor elements **30H**, **30L** configurations similar to each other. The semiconductor elements **30H**, **30L** are arranged in the X-direction. The semiconductor elements **30H**, **30L** are disposed at substantially the same position in the Z-direction.

[0075] The heatsink **40** is a wiring member disposed on the back surface side of the semiconductor element **30** in the Z-direction and electrically connected to the collector electrode **32** via solder **80**. The solder **80** connects (bonds) the heatsink **40** and the collector electrode **32**. The heatsink **40** corresponds to a back-side wiring member, and the solder **80** corresponds to a back-side bonding member. The heatsink **40** has a mounting surface **40a**, which is a surface facing the semiconductor element **30**, and a back surface **40b**, which is a surface opposite to the mounting surface **40a**. The solder **80** is interposed between a mounting surface **40a** of the heatsink **40** and the collector electrode **32** of the semiconductor element **30** to form a solder bonding part.

[0076] The heatsink **40** dissipates the heat of the semiconductor element **30** to the outside. As the heatsink **40**, for example, a metal plate made of Cu, a Cu alloy, or the like, a direct bonded copper (DBC) substrate, or the like can be adopted. The heatsink **40** may have a plating film of Ni, Au, or the like on the surface. In the present embodiment, the heatsink **40** is a metal plate made of Cu. The heatsink **40** may be referred to as a heat dissipation member, a conductive member, or a lead frame. The semiconductor device **10** includes two heatsinks **40**. Specifically, a heatsink **40H** constituting the upper arm **6H** and a heatsink **40L** constituting the lower arm **6L** are provided.

[0077] As illustrated in FIG. 6, each of the heatsinks **40H**, **40L** has a substantially rectangular planar shape. The heatsinks **40H**, **40L** are arranged in the X-direction. As illustrated in FIGS. 3 and 4, the heatsinks **40H**, **40L** have substantially the same thickness and are disposed at substantially the same position in the Z-direction. Solder bonding parts are formed between the mounting surface **40a** of the heatsink **40H** and the collector electrode **32** of the semiconductor element **30H** and between the mounting surface **40a** of the heatsink **40L** and the collector electrode **32** of the semiconductor element **30L**.

[0078] The heatsinks **40H**, **40L** enclose the corresponding semiconductor element **30** in a plan view from the Z-direction. The back surfaces **40b** of the heatsinks **40H**, **40L** are exposed from the sealing resin body **20**. The back surface **40b** may be referred to as a heat dissipation surface or an exposed surface. The back surface **40b** is substantially flush with the back surface **20b** of the sealing resin body **20**. The back surfaces **40b** of the heatsinks **40H**, **40L** are arranged in the X-direction.

[0079] The heatsink **50** and the terminal **55** are wiring members disposed on the front surface side of the semiconductor element **30** in the Z-direction and electrically connected to the emitter electrode **31** via the solder **81** and solder **82**. The terminal **55** is interposed between the semiconductor element **30** and the heatsink **50** in the Z-direction. The solder **81** connects (joins) the

terminal **55** and the emitter electrode **31**. The solder **82** connects (joins) the heatsink **50** and the terminal **55**.

[0080] The terminal **55** has a first end face **55a**, which is a surface facing the semiconductor element **30**, and a second end face **55b**, which is a surface opposite to the first end face **55a**. The heatsink **50** has a mounting surface **50a**, which is a surface facing the second end face **55b**, and a back surface **50b**, which is a surface opposite to the mounting surface **50a**. The mounting surface **50a** is a surface of the heatsink **50** on the semiconductor element **30** side. The solder **81** is interposed between the first end face **55a** of the terminal **55** and the emitter electrode **31** of the semiconductor element **30** to form a solder bonding part. The solder **82** is interposed between the second end face **55b** of the terminal **55** and the mounting surface **50a** of the heatsink **50** to form a solder bonding part. The heatsink **50** and the terminal **55** correspond to the front-side wiring member. The solder **81** corresponds to a front-side bonding member.

[0081] The terminal **55** is located in the middle of an electrical conduction and thermal conduction path between the semiconductor element **30** (emitter electrode **31**) and the heatsink **50**. The terminal **55** contains a metal material such as Cu or a Cu alloy. A plating film may be provided on the surface. Each of the terminals **55H**, **55L** is a columnar body that is substantially as large as the emitter electrode **31** and has a substantially rectangular planar shape in a plan view. The terminal **55** may be referred to as a metal block body or a relay member. The semiconductor device **10** includes two terminals **55**. Specifically, a terminal **55H** constituting the upper arm **6H** and a terminal **55L** constituting the lower arm **6L** are provided. Solder bonding parts are formed between the first end face **55a** of the terminal **55H** and the emitter electrode **31** of the semiconductor element **30H** and between the first end face **55a** of the terminal **55L** and the emitter electrode **31** of the semiconductor element **30L**.

[0082] The heatsink **50** dissipates the heat of the semiconductor element **30** to the outside. The heatsink **50** has a similar configuration to that of the heatsink **40**. In the present embodiment, the heatsink **50** is a metal plate made of Cu. The semiconductor device **10** includes two heatsinks **50**. Specifically, a heatsink **50H** constituting the upper arm **6H** and a heatsink **50L** constituting the lower arm **6L** are provided.

[0083] As illustrated in FIG. 5, the heatsinks **50H**, **50L** each have a substantially rectangular planar shape. The heatsinks **50H**, **50L** are arranged in the X-direction. As illustrated in FIGS. 3 and 4, the heatsinks **50H**, **50L** have substantially the same thickness and are disposed at substantially the same position in the Z-direction. Solder bonding parts are formed between the mounting surface **50a** of the heatsink **50H** and the second end face **55b** of the terminal **55H**, and between the mounting surface **50a** of the heatsink **50L** and the second end face **55b** of the terminal **55L**.

[0084] The heatsinks **50H**, **50L** enclose the corresponding semiconductor element **30** and terminal **55** in a plan view from the Z-direction. On the mounting surfaces **50a** of the heatsinks **50H**, **50L**, a groove **51** for holding the overflowing solder **82** is formed. The groove **51** surrounds the solder bonding part on the mounting surface **50a**. The groove **51** is formed in, for example, an annular shape. The back surfaces **50b** of the heatsinks **50H**, **50L** are exposed from the sealing resin body **20**. The back surface **50b** may be referred to as a heat dissipation surface or an exposed surface. The back surface **50b** is substantially flush with the front surface **20a** of the sealing resin body **20**. The back surfaces **50b** of the heatsinks **50H**, **50L** are arranged in the X-direction.

[0085] The couplings **60** to **62** couples between elements constituting the upper and lower arm circuit **6**. The coupling couples between elements constituting the semiconductor device **10**. As illustrated in FIGS. 3 and 6, the coupling **60** is continuous with the heatsink **40L**. The coupling **60** is thinner than the heatsink **40L**. The coupling **60** is continuous with a surface (side surface) facing the heatsink **40H** in the state of being substantially flush with the mounting surface **40a** of the heatsink **40L**. The coupling **60** has a substantially crank shape in the ZX plane by having two bent parts. The coupling **60** is covered with the sealing resin body **20**. The coupling **60** may be continuous with the heatsink **40L** by being provided integrally, or may be continuous with the

heatsink **40L** by connection while being provided separately. In the present embodiment, the coupling **60** is provided integrally with the heatsink **40L** as a part of the lead frame.

[0086] As illustrated in FIGS. **3** and **5**, the couplings **61**, **62** are continuous with the corresponding heatsinks **50**. The coupling **61** is continuous with the heatsink **50H**. The coupling **62** is continuous with the heatsink **50L**. The couplings **61**, **62** are thinner than the corresponding heatsink **50**. The couplings **61**, **62** are covered with a sealing resin body **20**. Each of the couplings **61**, **62** may be continuous with the heatsink **50** by being provided integrally, or may be continuous with the heatsink **50** by connection while being provided separately. In the present embodiment, the couplings **61**, **62** are provided integrally with the corresponding heatsinks **50H**, **50L**. The couplings **61**, **62** extend in the X-direction from the side surfaces facing each other in the two heatsinks **50H**, **50L**.

[0087] The heatsink **50H** including the coupling **61** and the heatsink **50L** including the coupling **62** are common members. The heatsink **50H** including the coupling **61** and the heatsink **50L** including the coupling **62** are disposed in two-fold rotational symmetry with the Z-axis as a rotation axis. Solder **83** is interposed between the facing surfaces of the coupling **60** and the coupling **61** to form a solder bonding part.

[0088] A groove **63** for holding the overflowing solder **83** is formed on the bonding surface of the coupling **61**. The groove **63** is formed in an annular shape so as to surround the solder bonding part. Similarly, a groove **63** for holding the overflowing solder is also formed on the bonding surface of the coupling **62**. In the present embodiment, the groove **63** is formed by press working. Therefore, each of the couplings **61**, **62** have a protrusion **64** on the back surface side of the groove **63**.

[0089] The main terminals **70** to **72** and the signal terminal **75** are external connection terminals. The main terminals **70**, **71** are power supply terminals. The main terminal **70** is electrically connected to the positive electrode terminal of the smoothing capacitor **4**. The main terminal **71** is electrically connected to the negative electrode terminal of the smoothing capacitor **4**. Therefore, the main terminal **70** may be referred to as a P terminal, and the main terminal **71** may be referred to as an N terminal.

[0090] As illustrated in FIGS. **5** and **6**, the main terminal **70** is continuous with one end of the heatsink **40H** in the Y-direction. The main terminal **70** is thinner than the heatsink **40H**. The main terminal **70** is substantially flush with the mounting surface **40a** and continuous with the heatsink **40H**. The main terminal **70** extends in the Y-direction from the heatsink **40H** and protrudes outward from the side surface **20c** of the sealing resin body **20**. The main terminal **70** has a bent part in the middle of a portion covered with the sealing resin body **20** and protrudes from the vicinity of the center in the Z-direction on the side surface **20c**.

[0091] As illustrated in FIGS. **4** and **5**, the main terminal **71** is connected to the coupling **62**. Solder **84** is interposed between the facing surfaces of the main terminal **71** and the coupling **62** to form a solder bonding part. The main terminal **71** extends in the Y-direction and protrudes from the same side surface **20c** as the main terminal **70** to the outside of the sealing resin body **20**. The main terminal **71** has a connection part **71a** with the coupling **62** near one end in the Y-direction. A portion of the main terminal **71** including the connection part **71a** is covered with the sealing resin body **20**, and the remaining part protrudes from the sealing resin body **20**. The connection part **71a** is thicker than a portion protruding from the sealing resin body **20**. The plate thickness of the connection part **71a** is substantially the same as the thickness of the heatsink **40**, for example. The main terminal **71** also has a bent part similarly to the main terminal **70** and protrudes from the vicinity of the center in the Z-direction on the side surface **20c**.

[0092] The main terminal **72** is connected to a connection point between the upper arm **6H** and the lower arm **6L**. The main terminal **72** is electrically connected to a winding (stator coil) of a corresponding phase of the motor generator **3**. The main terminal **72** is also referred to as an output terminal, an AC terminal, or an O terminal. The main terminal **72** is continuous with one end of the heatsink **40L** in the Y-direction. The main terminal **72** is thinner than the heatsink **40L**. The main

terminal 72 is substantially flush with the mounting surface 40a and continuous with the heatsink 40L. The main terminal 72 extends from the heatsink 40L in the Y-direction and protrudes from the same side surface 20c as the main terminal 70 to the outside of the sealing resin body 20. The main terminal 72 also has a bent part similarly to the main terminal 71 and protrudes from the vicinity of the center in the Z-direction on the side surface 20c. The three main terminals 70 to 72 are disposed in the order of the main terminal 70, the main terminal 71, and the main terminal 72 in the X-direction.

[0093] The signal terminal 75 is electrically connected to the pad 33 of the corresponding semiconductor element 30. In the present embodiment, the electrical connection is made via a bonding wire 87. The signal terminal 75 extends in the Y-direction and protrudes outward from the side surface 20d of the sealing resin body 20. The side surface 20d is a surface opposite to the side surface 20c in the Y-direction. In the present embodiment, five signal terminals 75 are provided for one semiconductor element 30.

[0094] Reference numeral 88 illustrated in FIGS. 2, 5, and 6 denotes a suspension lead. The heatsink 40 (40H, 40L), the coupling 60, the main terminals 70 to 72, and the signal terminal 75 are formed in a lead frame that is a common member. The lead frame is a counter stripe having a partially different thickness. The signal terminal 75 is connected to the suspension lead 88 via a tie bar in a state before cutting. An unnecessary portion of the lead frame such as the tie bar is cut (removed) after the molding of the sealing resin body 20.

[0095] As described above, in the semiconductor device 10, the plurality of semiconductor elements 30 constituting the upper and lower arm circuit 6 for one phase are sealed by the sealing resin body 20. The sealing resin body 20 integrally seals a part of each of the plurality of semiconductor elements 30 and the heatsink 40, a part of each of the heatsink 50, and a part of each of the terminal 55, the couplings 60 to 62, the main terminals 70 to 72, and the signal terminal 75.

[0096] In the Z-direction, the semiconductor element 30 is disposed between the heatsinks 40, 50. Thereby, the heat of the semiconductor element 30 can be dissipated to both sides in the Z-direction. The semiconductor device 10 has a double-sided heat dissipation structure. The back surface 40b of the heatsink 40 is substantially flush with the back surface 20b of the sealing resin body 20. The back surface 50b of the heatsink 50 is substantially flush with the front surface 20a of the sealing resin body 20. Since the back surfaces 40b, 50b are exposed surfaces, heat dissipation can be enhanced.

<Wire Piece>

[0097] Next, wire pieces will be described with reference to FIGS. 7 to 9. FIG. 7 is an enlarged plan view of the periphery of the semiconductor element 30H on the upper arm 6H side in FIG. 6. FIG. 7 illustrates a positional relationship between the semiconductor element and the wire pieces. In FIG. 7, the terminal 55H, the solder 81, the emitter electrode 31, the pad 33, and the bonding wire 87 are omitted for convenience. FIG. 8 is a perspective view illustrating an arrangement of wire pieces. FIG. 9 is a sectional view taken along a line IX-IX of FIG. 7.

[0098] As illustrated in FIGS. 7 to 9, the semiconductor device 10 further includes wire pieces 90. The wire piece 90 is provided in at least one of the solder bonding parts each electrically connecting the main electrode and the wiring member. The wire piece 90 is disposed in the solder. A plurality of wire pieces 90 are dispersedly arranged for one (single) solder. The plurality of wire pieces 90 are fixed (bonded) to a first facing surface that is one of facing surfaces constituting the solder bonding part, and protrude toward a second facing surface that is another one of the facing surfaces.

[0099] The wire piece 90 has a predetermined height in order to ensure the minimum film thickness of the solder. Even in a state where the plurality of wire pieces 90 are in contact with the second facing surface, the height of the wire piece 90 is set such that the shortest distance between the first facing surface and the second facing surface is equal to or more than the minimum film thickness. The minimum film thickness is the minimum thickness required for ensuring desired connection

reliability. The height of the wire piece **90** is, for example, a value obtained by adding a margin to the minimum film thickness. The wire piece **90** is a small piece of the bonding wire. The wire piece **90** may be referred to as a protruding portion or stud bonding.

[0100] In the present embodiment, a plurality of wire pieces **90** are arranged in the solder **80** between the collector electrode **32** of the semiconductor element **30H** and the mounting surface **40a** of the heatsink **40H**. All of the plurality of wire pieces **90** are fixed (bonded) to the mounting surface **40a** of the heatsink **40H** and are not fixed to the back surface of the semiconductor element **30H**, that is, onto the collector electrode **32**. The mounting surface **40a** of the heatsink **40H** corresponds to the first facing surface, and the back surface of the semiconductor element **30H** corresponds to the second facing surface. The plurality of wire pieces **90** are fixed to the mounting surface **40a**. The wire piece **90** is a small piece of a bonding wire made of aluminum or an aluminum alloy. All the wire pieces **90** fixed to the mounting surface **40a** are arranged in the solder **80**.

[0101] The solder **80** has a central region **80a** overlapping with the central portion of the semiconductor element **30H** and an outer peripheral region **80b** surrounding the central region **80a** in a plan view. The central portion of the semiconductor element **30H** is an element center **30c** and the peripheral portion thereof. The semiconductor element **30H** has an outer peripheral portion surrounding a central portion. The outer peripheral portion is, for example, a portion within a predetermined range from each of the four sides of the rectangular planar shape. For example, the central portion is an active region in which an element is formed, and the outer peripheral portion is an outer peripheral withstand voltage region surrounding the active region. The outer peripheral region **80b** includes a portion overlapping with the outer peripheral portion of the semiconductor element **30H**. A plurality of wire pieces **90** are arranged in each of the central region **80a** and the outer peripheral region **80b**.

[0102] The plurality of wire pieces **90a** as some of the wire pieces **90** fixed to the mounting surface **40a** are arranged in the central region **80a** so as to surround the element center **30c** in a plan view. A center line CL illustrated in FIG. 7 is an imaginary line passing through the element center **30c** and extending in the Z-direction. The wire pieces **90a** in the central region **80a** surround the center line CL. In order to surround the element center **30c**, three or more wire pieces **90a** are arranged in the central region **80a**. In the present embodiment, three wire pieces **90a** are arranged in the central region **80a**. The three wire pieces **90a** have a positional relationship of three-fold rotational symmetry with respect to the element center **30c**.

[0103] A plurality of wire pieces **90b**, which are the other of the wire pieces **90** fixed to the mounting surface **40a**, are arranged in the outer peripheral region **80b** so as to surround the element center **30c** in a plan view. The plurality of wire pieces **90b** are arranged corresponding to at least the four respective corners of the semiconductor element **30H** having a rectangular planar shape. Therefore, four or more wire pieces **90b** are arranged in the outer peripheral region **80b**. In the present embodiment, four wire pieces **90b** are arranged in the outer peripheral region **80b**. The wire pieces **90b** are arranged at portions overlapping with the four corners of the semiconductor element **30H**. The four corners do not refer to four corners (vertexes) of the rectangular planar shape but are portions of a predetermined range including the vertexes (portions around the corners).

[0104] A similar configuration is formed on the lower arm **6L** side. That is, a plurality of wire pieces **90** are arranged in the solder **80** between the collector electrode **32** of the semiconductor element **30L** and the mounting surface **40a** of the heatsink **40L**. The plurality of wire pieces **90** are fixed to the mounting surface **40a**. Therefore, a description is omitted.

<Method for Manufacturing Semiconductor Device>

[0105] Next, a method for manufacturing the semiconductor device **10** described above will be described. In the present embodiment, the semiconductor device **10** is formed using a solder die bond method.

[0106] First, the wire piece **90** is formed. An aluminum-based bonding wire is ultrasonically

bonded to the mounting surface **40a** of the heatsink **40** in the lead frame. The bonding wire typically has a first bonding part and a second bonding part in order to electrically connect two portions. Here, the wire is cut at the point when the first bonding part is formed to form the wire piece **90**.

[0107] Next, molten solder is applied to form a laminate. First, molten solder (solder **80**) is applied onto the mounting surface **40a**, and the semiconductor element **30** is disposed on the molten solder such that the collector electrode **32** is on the mounting surface **40a** side. Next, molten solder (solder **81**) is applied onto the emitter electrode **31** of the semiconductor element **30**, and the terminal **55** is disposed on the molten solder such that the first end face **55a** is on the semiconductor element **30** side. Further, molten solder (solder **82**) is applied onto the second end face **55b** of the terminal **55**. Molten solder (solder **83**, solder **84**) is also applied onto each of the coupling **60** and the connection part **71a**. The molten solder can be applied using, for example, a transfer method. The applied molten solder is solidified to obtain a laminate of the heatsink **40**, the semiconductor element **30**, and the terminal **55**.

[0108] All of the solder **80** to the solder **84** may be solidified at once or may be solidified in the order of lamination. By performing the solidification at once, the manufacturing process can be simplified (e.g., the manufacturing time can be shortened). The bonding wire **87** may be connected in the state of the laminate or may be connected in a state where the solder **80** is solidified before the solder **81** is applied. Bonding in the state of the laminate in which the application of all of the solder **80** to the solder **84** has been completed is preferable because it is possible to prevent defects due to contact of an application device or the like.

[0109] The semiconductor device **10** having the double-sided heat dissipation structure is sandwiched from both sides in the Z-direction by, for example, a cooler (not illustrated). Thus, high parallelism of the surfaces and high dimensional accuracy between the surfaces in the Z-direction are required. Therefore, the solder **82** is disposed in an amount capable of absorbing the height variation of the semiconductor device **10**. That is, a larger amount of solder **82** is disposed. For example, the solder **82** is thicker than the solder **80** and the solder **81**.

[0110] Next, the heatsink **50** is disposed on a mount (not illustrated) such that the mounting surface **50a** faces upward. The laminate is disposed on the heatsink **50** such that the solder **82** faces the mounting surface **50a** of the heatsink **50**, and reflow is performed. In the reflow, a load (outlined arrow) is applied in the Z-direction from the heatsink **40** side to set the height of the semiconductor device **10** to a predetermined height. Specifically, a load is applied to bring a spacer (not illustrated) into contact with both the mounting surface **40a** of the heatsink **40** and the placement surface of the mount. In this manner, the height of the semiconductor device **10** is set to the predetermined height.

[0111] The terminal **55** and the heatsink **50** are connected (bonded) via the solder **82** by reflow. That is, the emitter electrode **31** and the heatsink **50** are connected electrically. The solder **82** absorbs the height variation due to dimensional tolerance and assembly tolerance of elements constituting the semiconductor device **10**. For example, when the entire amount of the solder **82** is required in order to set the height of the semiconductor device **10** to the predetermined height, the entire amount of the solder **82** remains in a connection region inside the groove **51**. On the other hand, for the setting to the predetermined height, when a part of the solder **82** overflows, the overflowing solder **82** is held in the groove **51**. The same applies to the solder **83** and the solder **84**, and hence the description thereof will be omitted.

[0112] Next, the sealing resin body **20** is molded by a transfer molding method. Although not illustrated, in the present embodiment, the sealing resin body **20** is molded such that the heatsinks **40**, **50** are completely covered, and cutting is performed after molding. The sealing resin body **20** is cut together with a part of each of the heatsinks **40**, **50**. This makes the back surfaces **40b**, **50b** exposed. The back surface **40b** is substantially flush with the back surface **20b**, and the back surface **50b** is substantially flush with the front surface **20a**. The sealing resin body **20** may be molded in a state where the back surfaces **40b**, **50b** are pressed against and brought into close

contact with a cavity wall surface of a molding die. In this case, at the point when the sealing resin body **20** is molded, the back surfaces **40b**, **50b** are exposed from the sealing resin body **20**. This eliminates the need for cutting after molding.

[0113] Next, tie bars (not illustrated) and the like are removed, whereby the semiconductor device **10** can be obtained.

[0114] The example in which the heatsink **50** is disposed and the reflow is performed after the formation of the laminate has been shown, but the present disclosure is not limited thereto. After molten solder (solder **82**) is applied onto the second end face **55b** of the terminal **55**, the heatsink **50** may be disposed on the molten solder. Alternatively, all of the solder **80** to the solder **84** may be solidified at once to form a laminate including the heatsink **50** at once. That is, the semiconductor device **10** can be obtained without performing reflow.

Summary of First Embodiment

[0115] Reduction in the number of components, reduction in cost, and the like may be performed by using the heatsink **40** as a common component for semiconductor elements **30** of various types (a plurality of product numbers). The semiconductor element **30** has the emitter electrode **31** on the front surface and the collector electrode **32** on the back surface, and the areas of the emitter electrode **31** and the collector electrode **32** are different. In such a configuration, warpage may occur in different directions depending on the product type or depending on the film thickness, the film forming method, the chip size, the electrode area, or the like. For example, in one type, warpage toward the heatsink **40**, that is, downward, occurs and in another type, warpage toward the side opposite to the heatsink **40**, that is, upward, occurs. Even when the element size (chip size) is the same, the direction of warpage may be different because, for example, the film formation method (film configuration) is different. Furthermore, the direction of warpage may be different in the same product type due to variations in manufacturing conditions.

[0116] In contrast, in the present embodiment, a plurality of wire pieces **90** are provided in the solder bonding part between the collector electrode **32** of the semiconductor element **30** and the heatsink **40**. The wire piece **90** is fixed to the mounting surface **40a** of the heatsink **40**, which is the first facing surface, and protrudes on the back surface side of the semiconductor element **30**, which is the second facing surface. In the central region **80a** of the solder **80**, three or more wire pieces **90a** are arranged to surround the element center **30c**. In the outer peripheral region **80b** of the solder **80**, four or more wire pieces **90b** are arranged to correspond to at least the four respective corners of the semiconductor element **30**, respectively.

[0117] Therefore, as illustrated in FIG. **10**, when the semiconductor element **30** has warped downward, the minimum film thickness of the solder **80** can be ensured by the wire pieces **90a** that are disposed to surround the element center **30c**. For example, the semiconductor element **30** can be supported by three or more wire pieces **90a** arranged to surround the element center **30c**. As a result, the inclination of the semiconductor element **30** can be prevented to ensure the minimum film thickness throughout the surface.

[0118] When the semiconductor element **30** has warped upward, the minimum film thickness of the solder **80** can be ensured by the wire pieces **90b** arranged corresponding to at least the four corners of the semiconductor element **30**. For example, the semiconductor element **30** can be supported by the wire pieces **90b** arranged at least at the four corners. As a result, the inclination of the semiconductor element **30** can be prevented to ensure the minimum film thickness throughout the surface. As described above, even when the wire piece **90** comes into contact with the collector electrode **32**, the minimum film thickness of the solder **80** can be ensured by the height of the wire piece **90**.

[0119] Further, the wire piece **90** is fixed to the heatsink **40**. That is, the solder is not put into a melting furnace of the solder and applied together with the molten solder. The shape of the wire piece **90** can be maintained even when molten solder is applied.

[0120] As described above, the film thickness of the solder **80** can be ensured regardless of whether

the semiconductor element **30** has warped downward or upward. Even when various semiconductor elements **30** are used, the film thickness of the solder **80** can be ensured. This makes it possible to provide the semiconductor device **10** with high reliability. Since the solder thickness can be ensured, the detection accuracy of voids by an ultrasonic flaw detector (scanning acoustic tomograph (SAT)) can also be improved. Moreover, the cost can be reduced as compared to the method using Ni balls. In FIG. **10**, the solder **80** is omitted for convenience.

[0121] Although the example in which the wire piece **90** is fixed to the mounting surface **40a** of the heatsink **40** has been described, the configuration is not limited thereto. The wire piece **90** may be fixed to the collector electrode **32** of the semiconductor element **30**. That is, the back surface of the semiconductor element **30** may be the first facing surface. However, the structure in which the wire piece **90** is fixed to the heatsink **40** (back-side wiring member) is preferable because the influence at the time of bonding the wire piece **90** is small.

[0122] The number and arrangement of the wire pieces **90** are not limited to the above example. Depending on the warpage of the semiconductor element **30**, the wire pieces **90** may be arranged only in the central region **80a**, or the wire pieces **90** may be arranged only in the outer peripheral region **80b**. In the central region **80a**, four or more wire pieces **90a** may be arranged to surround the element center **30c**. In the outer peripheral region **80b**, the wire pieces **90b** may be arranged at the four corners as well as at portions except for the four corners. That is, five or more wire pieces **90b** may be arranged to surround the element center **30c**. The positions of the wire pieces **90** may be adjusted when the wire pieces **90** are provided in accordance with the magnitude (size) of the semiconductor element **30**.

[0123] The configuration of the semiconductor device **10** is not limited to the above example. For example, the terminal **55** may not be provided. In this case, it is sufficient that the emitter electrode **31** and the mounting surface **50a** of the heatsink **50** be connected. A protrusion may be provided on the mounting surface **50a** of the heatsink **50**, and a solder bonding part may be formed between the tip of the protrusion and the emitter electrode **31**.

[0124] The present embodiment can also be applied to a configuration not including the front-side wiring member, that is, the terminal **55** and the heatsink **50**. For example, a bonding wire may be connected to the emitter electrode **31** to connect the upper arm **6H** and the lower arm **6L** and to connect the main terminal. The wire piece **90** may be provided on only one of the solder **80** on the upper arm **6H** side and the solder **80** on the lower arm **6L** side.

Second Embodiment

[0125] The present embodiment is a modification with the preceding embodiment as a basic form, and the description of the preceding embodiment can be incorporated.

[0126] As described in the preceding embodiment, in the semiconductor device **10**, the wire piece **90** may be in contact with the second facing surface or may not be in contact with the second facing surface. Preferably, as illustrated in FIG. **11**, the wire piece **90** may not be into contact with the collector electrode **32** that is the second facing surface. FIG. **11** is a sectional view illustrating a periphery of a connection part between the semiconductor element and the heatsink in the semiconductor device **10** according to the present embodiment. FIG. **11** corresponds to FIG. **9**. In FIG. **11**, for convenience, the electrode on the front surface side of the semiconductor element **30** is omitted. The configuration of the semiconductor device **10** is similar to that in the first embodiment, for example. The configuration illustrated in FIG. **11** is the same on the upper arm **6H** side and the lower arm **6L** side.

[0127] The wire piece **90** is fixed to the mounting surface **40a** of the heatsink **40** and is disposed in the solder **80**. In the bonding part formed of the solder **80**, the mounting surface **40a** forms a first facing surface, and the front surface of the collector electrode **32** forms a second facing surface. A protrusion height **H1** of the wire piece **90** with reference to the mounting surface **40a** is less than a thickness **T1** of the solder **80**. The wire piece **90** is not in contact with the collector electrode **32** and has a gap from the collector electrode **32**. The protrusion height **H1** is a height that can ensure

the minimum film thickness as described above. The protrusion height **H1** is, for example, about 50 to 100 μm . The target value of the solder **80** is, for example, about 150 μm .

Summary of Second Embodiment

[0128] According to the present embodiment, the protrusion height **H1** of the wire piece **90** is less than the thickness **T1** of the solder **80**. Therefore, at the time of forming the semiconductor device **10**, the wire piece **90** does not come into contact with the second facing surface. It is possible to prevent the collapse of the wire piece **90** due to contact and thus ensure a predetermined solder thickness.

[0129] In the present embodiment, the main electrode is the second facing surface. That is, the wire piece **90** is fixed to the surface facing the main electrode. Therefore, by satisfying the condition that the protrusion height **H1** is less than the thickness **T1** of the solder **80**, it is also possible to prevent the wire piece **90** from coming into contact with the collector electrode **32** and damaging the collector electrode **32**.

[0130] Although the example in which the above relationship is applied to the configuration of the first embodiment has been shown, the present disclosure is not limited thereto. For example, the present embodiment can also be applied to a configuration in which the number of wire pieces **90** arranged in the solder **80** is different from that in the first embodiment (e.g., a total of three). The number of wire pieces **90** disposed in the solder **80** may be plural, preferably three or more. The configuration described in the first embodiment is more preferable.

[0131] The present embodiment is not limited to the wire piece **90** in the solder **80**. The present embodiment can be applied to any solder in which the wire piece **90** is disposed. It is particularly suitable for a solder bonding part of a main electrode. For example, when the present embodiment is applied to a configuration in which the wire piece **90** is provided in the solder **81** and the wire piece **90** is fixed to the terminal **55**, a predetermined solder thickness can be ensured, and damage to the emitter electrode **31** can be prevented. Only one of the upper arm **6H** side and the lower arm **6L** side may satisfy the above relationship.

Third Embodiment

[0132] The present embodiment is a modification with the preceding embodiment as a basic form, and the description of the preceding embodiment can be incorporated.

[0133] In the present embodiment, the wire pieces **90** are disposed only in the outer peripheral region **80b** as illustrated in FIG. 12. FIG. 12 is a plan view illustrating a positional relationship between the semiconductor element **30** and the wire pieces **90** in the semiconductor device **10** of the present embodiment. FIG. 12 corresponds to FIG. 7. The wire pieces **90** are arranged at positions corresponding to at least the four respective corners of the semiconductor element **30** in the outer peripheral region **80b**. In FIG. 12, the wire pieces **90** are arranged only at the four corners. The wire piece **90** is not disposed in the central region **80a**. The configuration illustrated in FIG. 12 is the same on the upper arm **6H** side and the lower arm **6L** side.

[0134] Although not illustrated, the emitter electrode **31** of the semiconductor element **30** includes a base electrode part formed on the surface of the semiconductor substrate using an Al-based material such as AlSi and a connection electrode part formed on the base electrode part. The base electrode part is formed by, for example, a sputtering method. The connection electrode part is formed by a plating method. The connection electrode part includes, for example, a Ni layer formed on the base electrode part and an Au layer formed on the Ni layer. The collector electrode **32** is formed by the sputtering method. The collector electrode **32** includes an Al layer formed on the back surface of the semiconductor substrate using an Al-based material such as AlSi, and a Ni layer formed on the Al layer. The emitter electrode **31** using the plating method is thicker than the collector electrode **32**.

Summary of Third Embodiment

[0135] FIG. 13 is a sectional view taken along a line XIII-XIII of FIG. 12 and illustrates a connection structure between the semiconductor element **30** and the heatsink **40**. In the electrode

configuration described above, the semiconductor element **30** can warp downward as illustrated in FIG. **13**. In the present embodiment, the supply amount of the solder **80** is set so as to ensure the minimum film thickness of the solder **80**. The solder **80** is supplied so as to ensure a predetermined thickness equal to or more than the minimum film thickness in a state where the bonding part between the semiconductor element **30** (collector electrode **32**) and the heatsink **40** wets and spreads. As illustrated in FIG. **13**, the semiconductor element **30** is supported by the solder **80** and is not in contact with the wire piece **90**. During soldering, the semiconductor element **30** floats on the molten solder. The solder **80** is supplied such that the solder thickness between the tip of the convex of the semiconductor element **30**, that is, the element center, and the heatsink **40** can ensure the minimum film thickness. FIG. **13** illustrates an ideal state in which there is no inclination in the placement of the semiconductor element **30** with respect to the heatsink **40**.

[0136] FIG. **14** is a sectional view when semiconductor element **30** is disposed in an inclined manner. As illustrated in FIG. **14**, when the semiconductor element **30** having warped downward is disposed in an inclined manner, the semiconductor element **30** comes into contact with some of the plurality of wire pieces **90**. By the wire pieces **90** supporting the semiconductor element **30**, the minimum film thickness of the solder **80** is ensured. The wire piece **90** has a height that can ensure the minimum film thickness of the solder **80** when the semiconductor element **30** having warped is disposed in an inclined manner. Since the wire pieces **90** are arranged at least at the four corners of the outer peripheral region **80b**, the semiconductor element **30** can be supported by at least one of the wire pieces **90** even when the semiconductor element **30** is inclined in any direction. As described above, according to the semiconductor device **10** of the present embodiment, even when the semiconductor element **30** has warped downward, the film thickness of the solder **80** can be ensured. It is thus possible to provide the semiconductor device **10** with high reliability (connection reliability).

[0137] The electrode configuration in which the semiconductor element **30** has warped downward is not limited to the above example.

[0138] In the outer peripheral region **80b**, the wire pieces **90** may be arranged at the four corners as well as at portions except for the four corners. That is, five or more wire pieces **90b** may be arranged to surround the element center **30c**.

Fourth Embodiment

[0139] The present embodiment is a modification with the preceding embodiment as a basic form, and the description of the preceding embodiment can be incorporated.

[0140] The extending direction of the wire piece **90** is not particularly limited on the first facing surface. The wire piece **90** can be extended in any direction. Preferably, the wire piece **90** may extend in a predetermined direction illustrated in FIG. **15**. FIG. **15** is a plan view illustrating a periphery of a connection part between the semiconductor element and the heatsink in the semiconductor device **10** according to the present embodiment. FIG. **15** corresponds to FIG. **7**. In FIG. **15**, in order to clarify the wire piece **90**, the semiconductor element **30** is indicated by a one-dot chain line, and the wire piece **90** is indicated by a solid line. The configuration of the semiconductor device **10** is similar to that in the first embodiment, for example. The configuration illustrated in FIG. **15** is the same on the upper arm **6H** side and the lower arm **6L** side.

[0141] The wire piece **90** is fixed to the mounting surface **40a** of the heatsink **40**. The number and arrangement of the wire pieces **90** are similar to those in the first embodiment (cf. FIG. **7**). In the present embodiment, the wire piece **90** extends toward the element center **30c** in a plan view. That is, the extending direction (longitudinal direction) of the wire piece **90** is substantially parallel to an imaginary line connecting the wire piece **90** and the element center **30c**. The wire piece **90** extends along the imaginary line. Of the wire pieces **90**, all three wire pieces **90a** arranged in the central region **80a** of the solder **80** extend toward the element center **30c**. All four wire pieces **90b** arranged in the outer peripheral region **80b** of the solder **80** extend toward the element center **30c**.

Summary of Fourth Embodiment

[0142] According to the present embodiment, since the wire piece **90** extends toward the element center **30c**, when the applied molten solder wets and spreads, the wire piece **90** hardly obstructs the flow thereof. It is thereby possible to prevent generation of voids in the solder **80** and generation of an unfilled portion between the facing surfaces. By setting at least one of the plurality of wire pieces **90** in the extending direction described above, a considerable effect can be obtained. In the present embodiment, all the wire pieces **90** arranged in the solder **80** extend toward the element center **30c**. As a result, it is possible to enhance the effect described above and thus enhance connection reliability.

[0143] Although the example in which the above relationship is applied to the configuration of the first embodiment has been shown, the present disclosure is not limited thereto. For example, the present embodiment can also be applied to a configuration in which the number and arrangement of the wire pieces **90** arranged in the solder **80** are different from those in the first embodiment. For example, as in a modification illustrated in FIG. **16**, the present embodiment may be applied to the configuration of the third embodiment (cf. FIG. **12**). The wire pieces **90** arranged in the outer peripheral region **80b** of the solder **80** extend toward the element center **30c**. Hence it is possible to enhance connection reliability while obtaining the effects described in the third embodiment. By setting at least one of the plurality of wire pieces **90** in the extending direction described above, a considerable effect can be obtained. In FIG. **16**, all the wire pieces **90** arranged in the outer peripheral region **80b** extend toward the element center **30c**. Therefore, connection reliability can be further improved.

[0144] The control of the extending direction is not limited to the wire piece **90** in the solder **80**. The present embodiment can be applied to any solder in which the wire piece **90** is disposed. For example, when the wire piece **90** is disposed in the solder **81**, the present embodiment may be applied to this wire piece **90**. When the wire piece **90** is disposed in the solder **82**, the present embodiment may be applied to this wire piece **90**. In addition, the extending direction described above may be achieved by only one of the upper arm **6H** side and the lower arm **6L** side.

[0145] In consideration of solder deformation, the extension length may be set as follows. When the extension length of the wire piece **90** is equal to or less than a predetermined length in a plan view, solder deformation is maximized at the end (outer peripheral end) of the solder **80**. On the other hand, when the extension length exceeds the predetermined length, the solder deformation is maximized at the end of the wire piece **90**. When the extension length increases, the solder deformation at the end of the wire piece increases, and when the extension length exceeds the predetermined length, the magnitude relationship of the solder deformation between the end of the wire piece and the end of the solder is reversed. Therefore, the extension length is preferably set within a range in which the solder deformation at the end of the wire piece **90** does not exceed the solder deformation at the end of the solder **80**. For example, the length of the wire piece **90** may be set to 350 μm or less with respect to 80 μm of the diameter of the aluminum-based bonding wire forming the wire piece **90**. Specifically, the length may be set within a range of 200 to 350 μm .

Fifth Embodiment

[0146] The present embodiment is a modification with the preceding embodiment as a basic form, and the description of the preceding embodiment can be incorporated.

[0147] As illustrated in FIGS. **17** to **19**, the wire piece **90** may be disposed in the solder **81** that bonds the front electrode and the front-side wiring member. At this time, the wire pieces **90** may be arranged at the positions illustrated in FIGS. **17** to **19**. FIG. **17** illustrates a positional relationship between the wire pieces **90** arranged in the solder **81** and the semiconductor element **30** in the semiconductor device **10** according to the present embodiment. FIG. **18** illustrates the arrangement of the wire pieces **90** in the terminal **55**. FIG. **19** is a sectional view taken along a line XIX-XIX of FIG. **17**. In FIG. **19**, for convenience, the gate wiring **34** is omitted. The configuration of the semiconductor device **10** of the present embodiment is, for example, similar to that in the first embodiment. The configuration of the wire pieces **90** arranged in the solder **81** are the same on the

upper arm **6H** side and the lower arm **6L** side.

[0148] The plurality of wire pieces **90** are provided in a solder bonding part between the emitter electrode **31** of the semiconductor element **30** and the first end face **55a** of the terminal **55**. All of the plurality of wire pieces **90** are fixed (bonded) to the first end face **55a** of the terminal **55** and are not fixed onto the emitter electrode **31** of the semiconductor element **30**, that is, to the surface. The first end face **55a** of the terminal **55** corresponds to a first facing surface, and the front surface of the semiconductor element **30** corresponds to a second facing surface. A plurality of wire pieces **90** are fixed to the first end face **55a**. All the wire pieces **90** fixed to the first end face **55a** are arranged in the solder **81**.

[0149] The semiconductor element **30** includes the gate pad **33g** as described above. The semiconductor element **30** includes gate wiring **34** formed on the front surface side and continuous with the gate pad **33g**, and a gate wiring protection part **35** that is a portion of the protective film formed on the front surface and protects the gate wiring **34**. The emitter electrode **31** is divided into two in the X-direction, and the gate wiring **34** is formed using aluminum or the like as a material between the adjacent emitter electrodes **31**.

[0150] A protective film is formed using polyimide or the like as a material on the front surface of the semiconductor element **30**, and the emitter electrode **31** and the pad **33** are exposed from the protective film. The gate wiring protection part **35** is a portion being a part of the protective film and covering the gate wiring **34**. In FIG. **17**, a portion of the gate wiring protection part **35** overlapping with the terminal **55** in a plan view is indicated as a region of a broken line. In FIG. **18**, for illustrating the positional relationship, the gate wiring protection part **35** is illustrated as a region of a one-dot chain line on the first end face **55a** of the terminal **55**.

[0151] The wire pieces **90** are arranged at positions not overlapping with the gate wiring protection part **35** in a plan view. As illustrated in FIGS. **17** and **18**, one wire piece **90** is fixed near the center of the first end face **55a** and at a position not overlapping with the gate wiring protection part **35**. The wire pieces **90** are fixed to the four respective corners of the first end face **55a** having a substantially rectangular planar shape. In this manner, the five wire pieces **90** are fixed to the first end face **55a**.

Summary of Fifth Embodiment

[0152] In the present embodiment, the plurality of wire pieces **90** are arranged in the solder **81**. This makes it possible to ensure the minimum film thickness of the solder **81**.

[0153] All of the wire pieces **90** in the solder **81** are provided at positions not overlapping with the gate wiring protection part **35** in a plan view. Thus, at the time of forming the semiconductor device **10**, it is possible to prevent the wire piece **90** from coming into contact with the gate wiring protection part **35** and damaging the protective film. Therefore, it is possible to prevent the occurrence of a short circuit between the gate electrode and the emitter electrode **31**, that is, a gate leak failure, due to the solder **81** entering the gate wiring **34** side from the damaged portion of the protective film.

[0154] The emitter electrode **31** is smaller in area than the collector electrode **32**. In other words, the bonding part of the solder **81** is smaller than the bonding part of the solder **80** in a plan view. Thus, even when the semiconductor element **30** warps upward, the semiconductor element **30** can be supported by one wire piece **90** provided near the center of the first end face **55a**. This makes it possible to ensure the minimum film thickness of the solder **81**. Even when the semiconductor element **30** warps downward, the semiconductor element **30** can be supported by the wire pieces **90** arranged at the four corners. This makes it possible to ensure the minimum film thickness of the solder **81**. Accordingly, it is possible to provide the semiconductor device **10** with high reliability.

[0155] Although the example in which the wire piece **90** is fixed to the first end face **55a** of the terminal **55** has been described, the present disclosure is not limited thereto. The wire piece **90** may be fixed to the emitter electrode **31** of the semiconductor element **30**. That is, the front surface of the semiconductor element **30** may be the first facing surface. However, the structure in which the

wire piece **90** is fixed to the terminal **55** (front-side wiring member) is preferable because the influence at the time of bonding the wire piece **90** is small.

[0156] The number and arrangement of the wire pieces **90** in the solder **81** are not limited to the above example. The wire piece **90** can be disposed in a range satisfying a condition that the wire piece **90** does not overlap with the gate wiring protection part **35** in a plan view. For example, a plurality of wire pieces **90** may be arranged near the center of the first end face **55a**. Further, in the vicinity of the outer peripheral end of the first end face **55a**, the wire pieces **90** may be arranged at four corners as well as portions except for the four corners. The above arrangement may be achieved by only one of the upper arm **6H** side and the lower arm **6L** side.

[0157] Although the example in which the above relationship is applied to the configuration of the first embodiment has been shown, the present disclosure is not limited thereto. At least one of the configuration of the second embodiment, the configuration of the third embodiment, and the configuration of the fourth embodiment may be combined with the wire pieces **90** arranged in the solder **81**. For example, the present embodiment can also be applied to a configuration in which the number of wire pieces **90** arranged in the solder **80** is different from that in the first embodiment. For example, the number of wire pieces **90** arranged in each of the solder **80** and the solder **81** may be the same.

[0158] In a modification illustrated in FIG. **20**, the wire pieces **90** are arranged at the four corners of the outer peripheral region **80b** of the solder **80**, and the wire pieces **90** are arranged at the four corners of the solder **81**. That is, four wire pieces **90** are arranged in each of the solder **80** and the solder **81**. Even when the semiconductor element **30** warps downward, the semiconductor element **30** can be supported by the wire pieces **90** disposed in the solder **81**. This makes it possible to ensure the minimum film thickness of the solder **81**. The wire pieces **90** in the solder **81** are arranged at positions not overlapping with the gate wiring protection part **35**. The wire pieces **90** arranged in the solder **80** and the solder **81** extend toward the element center **30c** similarly to the configuration illustrated in FIG. **16**. FIG. **20** is a plan view of the terminal **55** as viewed from the second end face side. In FIG. **20**, the wire piece **90** disposed in the solder **80** is indicated by a broken line, and the wire piece **90** disposed in the solder **81** is indicated by a one-dot chain line.

[0159] The wire piece **90** may be disposed in the solder **80** as described above without disposing the wire piece **90** in the solder **81**. The configuration of the present embodiment can also be applied to a configuration not including the back-side wiring member, that is, the heatsink **40**.

[0160] Although the example in which the semiconductor device **10** includes the terminal **55** has been described, the present disclosure is not limited thereto. The present embodiment can also be applied to a configuration not including the terminal **55**. For example, in the solder bonding part between the emitter electrode **31** and the mounting surface **50a** of the heatsink **50**, the wire piece **90** may be fixed to the mounting surface **50a** of the heatsink **50**.

Sixth Embodiment

[0161] The present embodiment is a modification with the preceding embodiment as a basic form, and the description of the preceding embodiment can be incorporated.

[0162] When the wire pieces **90** are arranged on each of the solder **80** and the solder **81**, the arrangement of the wire pieces **90** is not particularly limited. The wire pieces **90** may be arranged as illustrated in FIG. **21**. FIG. **21** is a plan view of the terminal as viewed from the second end face side in the semiconductor device **10** according to the present embodiment. FIG. **21** corresponds to FIG. **7**. The configuration of the semiconductor device **10** is similar to that in the first embodiment, for example. The configuration illustrated in FIG. **21** is the same on the upper arm **6H** side and the lower arm **6L** side.

[0163] The semiconductor device **10** includes a plurality of wire pieces **90** arranged in the solder **80** and a plurality of wire pieces **90** arranged in the solder **81**. Hereinafter, the wire piece **90** disposed in the solder **80** may be referred to as a wire piece **900**, and the wire piece **90** disposed in the solder **81** may be referred to as a wire piece **901**. In FIG. **21**, the wire piece **900** is indicated by a broken

line, and the wire piece **901** is indicated by a one-dot chain line.

[0164] The wire pieces **900** are arranged similarly to the wire pieces **90** (cf. FIG. 7) described in the first embodiment. The wire piece **900** is fixed to, for example, the mounting surface **40a** of the heatsink **40**. In the central region **80a** of the solder **80**, three wire pieces **900** are arranged to surround the element center **30c**. In the outer peripheral region **80b**, four wire pieces **900** are arranged corresponding to the four respective corners of the semiconductor element **30**.

[0165] The wire pieces **901** are arranged similarly to the wire pieces **90** (cf. FIG. 17) described in the fifth embodiment. The wire piece **901** is fixed to, for example, the first end face **55a** of the terminal **55**. One wire piece **901** is disposed near the center of the first end face **55a**. The wire pieces **901** are arranged at the four corners of the first end face **55a**. As illustrated in FIG. 21, the wire pieces **900** and the wire pieces **901** are arranged at positions not overlapping with each other in a plan view.

Summary of Sixth Embodiment

[0166] FIG. 22 is a schematic diagram illustrating the difference between a comparative example and the present example (present embodiment). In the comparative example, the same or related elements as or to the elements of the present embodiment (the present example) are indicated by adding r to the end of the reference numerals in the present embodiment. In FIG. 22, for convenience, the main electrode of the semiconductor element is omitted.

[0167] Wire pieces **900r**, **901r** are formed using an aluminum-based material as described above and have lower wettability by solder **80r** and solder **81r** than those of the main electrode (not illustrated) of a semiconductor element **30r**, a heatsink **40r**, and a terminal **55r**. Therefore, gaps **86r** are formed between the wire pieces **900r**, **901r** and the solder **80r** and the solder **81r**. The gap **86r** prevents heat conduction. As in the comparative example, when the wire pieces **900r**, **901r** overlap with each other in a plan view, the gaps **86r** also overlap. Since the gaps **86r** exist on both sides in the Z-direction with respect to the semiconductor element **30r**, it is difficult to release heat in the Z-direction from the portions of the semiconductor element **30r** overlapping with the gaps **86r** (wire pieces **900r**, **901r**). This causes an increase in thermal resistance.

[0168] In the present embodiment (present example) as well, similarly to the comparative example, the gaps **86** are formed between the wire piece **900** and the solder **80** and between the wire piece **901** and the solder **81**. However, since the wire pieces **900**, **901** are arranged at positions not overlapping with each other in a plan view, the gaps **86** in the solder **80** and the solder **81** do not overlap with each other in a plan view, or even when the gaps **86** overlap, the overlapping portion is very small. Hence the heat of the semiconductor element **30** can be released to at least one side in the Z-direction. As a result, the thermal resistance can be reduced and the heat dissipation can be enhanced as compared to the comparative example. In another embodiment, the gap **86** is omitted in the drawing.

[0169] In the present embodiment, the wire piece **900** has a similar configuration to that in the first embodiment. Therefore, in addition to the effects described in the present embodiment, the effects described in the first embodiment can also be obtained. The wire pieces **901** are configured and arranged in the same manner as in the fifth embodiment. Therefore, in addition to the effects described in the present embodiment, the effects described in the fifth embodiment can also be obtained. However, the number and arrangement of the wire pieces **900**, **901** can be selected within a range satisfying a condition that the wire pieces **900**, **901** do not overlap with each other in a plan view. That is, the number and arrangement are not limited to the above examples.

[0170] For example, only the wire piece **900** may have a similar configuration to that of the first embodiment, and the wire piece **901** may have a configuration different from that of the fifth embodiment. Only the wire piece **901** may have a similar configuration to that of the fourth embodiment, and the wire piece **900** may have a configuration different from that of the first embodiment. The number of wire pieces **900**, **901** may be the same. In the configuration illustrated in FIG. 20, the number of wire pieces **90** of the solder **80** and the number of wire pieces **90** of the

solder **81** are the same. The wire pieces **90** on the solder **80** side corresponding to the wire pieces **900** and the wire pieces **90** on the solder **81** side corresponding to the wire pieces **901** are arranged at positions not overlapping with each other in a plan view.

[0171] Although the example in which the wire piece **900** is fixed to the heatsink **40** has been described, the wire piece **900** may be fixed to the back surface (collector electrode **32**) of the semiconductor element **30**. Although the example in which the wire piece **901** is fixed to the terminal **55** has been described, the wire piece **901** may be fixed to the front surface (emitter electrode **31**) of the semiconductor element **30**. The wire piece **900** may be fixed to the heatsink **40**, and the wire piece **901** may be fixed to the semiconductor element **30**. The wire piece **900** may be fixed to the semiconductor element **30**, and the wire piece **901** may be fixed to the terminal **55**. The terminal **55** may not be provided. In this case, the wire piece **901** is provided in the solder bonding part between the heatsink **50** and the semiconductor element **30** (emitter electrode **31**).

[0172] The configuration of the present embodiment may be combined with at least one of the configuration of the second embodiment, the configuration of the third embodiment, and the configuration of the fourth embodiment. The configuration of the second embodiment may be combined with at least one of the wire pieces **900**, **901**. The configuration of the third embodiment may be combined with at least one of the wire pieces **900**, **901**. The configuration of the fourth embodiment may be combined with at least one of the wire pieces **900**, **901**. The configuration of the present embodiment may be achieved by only one of the upper arm **6H** side and the lower arm **6L** side.

Seventh Embodiment

[0173] The present embodiment is a modification with the preceding embodiment as a basic form, and the description of the preceding embodiment can be incorporated.

[0174] As illustrated in FIG. **23**, the wire piece **90** may be disposed in the solder **82**. At this time, the wire pieces **90** of the solder **80**, the solder **81**, and the solder **82** may be arranged as illustrated in FIG. **24**. FIG. **23** is a schematic sectional view illustrating a laminate between the heatsinks **40**, **50** in the semiconductor device **10** according to the present embodiment. FIG. **24** is a plan view illustrating an example of a preferable arrangement of the wire pieces **90** in each of the solder **80**, the solder **81**, and the solder **82**. FIG. **24** corresponds to FIG. **21**. In FIG. **24**, the wire piece **900** is indicated by a broken line, and the wire piece **901** is indicated by a one-dot chain line. The configuration of the semiconductor device **10** of the present embodiment is, for example, similar to that in the first embodiment. The configurations illustrated in FIGS. **23** and **24** are substantially the same on the upper arm **6H** side and the lower arm **6L** side.

[0175] As illustrated in FIG. **23**, a plurality of wire pieces **90** are arranged in each of the solder **80**, the solder **81**, and the solder **82**. Hereinafter, the wire piece **90** disposed in the solder **80** may be referred to as a wire piece **900**, the wire piece **90** disposed in the solder **81** may be referred to as a wire piece **901**, and the wire piece **90** disposed in the solder **82** may be referred to as a wire piece **902**. The number of wire pieces **90** is different among the solder **80**, the solder **81**, and the solder **82**. The number of wire pieces **900** is the largest, and the number of wire pieces **902** is the smallest. The number of wire pieces **901** is smaller than the number of wire pieces **900** and larger than the number of wire pieces **902**.

[0176] In FIG. **23**, the wire piece **900** is fixed to the heatsink **40**. The wire piece **901** is fixed to the first end face **55a** of the terminal **55**, and the wire piece **902** is fixed to the second end face **55b**.

[0177] As illustrated in FIG. **24**, the wire pieces **900** are arranged similarly to the wire pieces **90** (cf. FIG. **7**) described in the first embodiment. The wire piece **900** is fixed to the mounting surface **40a** of the heatsink **40**. In the central region **80a** of the solder **80**, three wire pieces **900** are arranged to surround the element center **30c**. In the outer peripheral region **80b**, four wire pieces **900** are arranged corresponding to the four respective corners of the semiconductor element **30**.

[0178] The wire pieces **901** are arranged similarly to the wire pieces **90** (cf. FIG. **17**) described in the fifth embodiment. The wire piece **901** is fixed to the first end face **55a** of the terminal **55**. One

wire piece **901** is disposed near the center of the first end face **55a**. The wire pieces **901** are arranged at the four corners of the first end face **55a**.

[0179] The wire piece **902** is fixed to the second end face **55b** of the terminal **55**. Three wire pieces **902** are fixed to the second end face **55b**. The plurality of wire pieces **902** are arranged to surround the element center **30c**. As illustrated in FIG. **24**, the wire pieces **900**, **901**, **902** are arranged at positions not overlapping with each other in a plan view. The terminal **55** corresponds to a first wiring member, and the heatsink **50** corresponds to a second wiring member. The solder **81** corresponds to a first bonding member that is a front-side bonding member, and the solder **82** corresponds to a second bonding member.

Summary of Seventh Embodiment

[0180] In the present embodiment, a plurality of wire pieces **90** are arranged in the solder **82**. It is thus possible to ensure the minimum film thickness of the solder **82**. A plurality of wire pieces **90** are arranged in each of the solder **80**, the solder **81**, and the solder **82**. Hence it is possible to ensure the minimum film thickness for all of the solder **80**, the solder **81**, and the solder **82** constituting the electrical conduction path and the thermal conduction path from the semiconductor element **30** to the heatsinks **40**, **50** on both sides in the Z-direction.

[0181] In the present embodiment, the number of wire pieces **90** to be arranged is different among each of the solder **80**, the solder **81**, and the solder **82**. The largest number of wire pieces **90** (wire pieces **900**) are arranged in the solder **80** on the collector electrode **32** side having a large electrode area. On the emitter electrode **31** side having an electrode area smaller than that of the collector electrode **32**, a smaller number of wire pieces **90** (wire pieces **901**) than the wire pieces **900** are arranged in the solder **81** on the side closer to the semiconductor element **30**. The smallest number of wire pieces **90** (wire pieces **902**) are arranged in the solder **82** on the side far from the semiconductor element **30**. Specifically, the semiconductor device **10** includes seven wire pieces **900**, five wire pieces **901**, and three wire pieces **902** as the wire pieces **90**.

[0182] The solder **80** and the solder **81** are affected by the warpage of the semiconductor element **30**. The largest number of wire pieces **90** are arranged in the solder **80** having the largest area in a plan view by the connection to the collector electrode **32**, so that the minimum film thickness of the solder **80** can be ensured. By arranging the wire pieces **900** in the same manner as in the first embodiment, the minimum film thickness can be ensured against the warpage of the semiconductor element **30**. The solder **81** connects the emitter electrode **31** having an area smaller than that of the collector electrode **32** and the terminal **55** that is a metal block body. By providing one wire piece **90** near the center, it is possible to cope with the upward warpage of the semiconductor element **30**. The minimum film thickness of the solder **81** can be ensured by arranging the wire piece **90** in smaller number than those in the solder **80**. By arranging the wire pieces **901** in the same manner as in the fifth embodiment, the minimum film thickness can be ensured even against the warpage of the semiconductor element **30**.

[0183] The solder **82** connects the terminal **55** and the heatsink **50**. The terminal **55** and the heatsink **50** are not warped unlike the semiconductor element **30**. In addition, since the terminal **55** is present between the solder **82** and the semiconductor element **30**, the solder **82** is not affected by the warpage of the semiconductor element **30**. Hence the minimum film thickness of the solder **82** can be ensured with the smallest number of wire pieces **90**. By making the number of the wire pieces **901** and the number of wire pieces **902** smaller than the number of the wire pieces **900**, it is possible to reduce the gaps **86** in the solder **81** and solder **82** as compared to the configuration in which the number of the wire pieces **900** is the same. It is thus possible to ensure the heat dissipation while ensuring the minimum film thickness. Moreover, since the number of the wire pieces **902** is made smaller than that of the wire pieces **901**, heat dissipation can be enhanced as compared to a configuration in which the number of the wire pieces **901** is the same. Also, the number of wire pieces **90** in the entire semiconductor device **10** can be reduced.

[0184] The wire pieces **900**, **901**, **902** are arranged at positions not overlapping with each other in a

plan view. The gaps **86** do not overlap with each other in the Z-direction, or even when the gaps **86** overlap, the overlapping portion is very small, so that heat dissipation can be enhanced.

[0185] When the numbers of wire pieces **90** in the solder **80**, the solder **81**, and the solder **82** are made different from each other, the numbers are not limited to the above example. It is sufficient that the relationship of the number of wire pieces **900** > the number of wire pieces **901** > the number of wire pieces **902** be satisfied. The relationship may be the number of wire pieces **900** > the number of wire pieces **901** = the number of wire pieces **902**. The relationship may be the number of wire pieces **900** = the number of wire pieces **901** > the number of wire pieces **902**. By making some of the wire pieces **90** of the solder **80**, the solder **81**, and the solder **82** different from the remaining wire pieces **90**, the effect is weakened, but the heat dissipation can be improved, and the wire pieces **90** can be reduced.

[0186] When the minimum film thickness is ensured in each of the solder **80**, the solder **81**, and the solder **82**, the number of the wire pieces **90** can be set more freely. The number of wire pieces **90** in the solder **80**, the solder **81**, and the solder **82** may be the same. Arranging a plurality of wire pieces, preferably three or more wire pieces **90**, facilitates ensuring the solder thickness.

[0187] The configuration of the present embodiment may be achieved by only one of the upper arm **6H** side and the lower arm **6L** side. Although the example in which the wire pieces **90** are arranged in the solder **80**, the solder **81**, and the solder **82** has been described, the wire piece may be further disposed on at least one of the solder **83** and the solder **84**.

Eighth Embodiment

[0188] The present embodiment is a modification with the preceding embodiment as a basic form, and the description of the preceding embodiment can be incorporated.

[0189] The shape of the terminal **55** is not particularly limited. Preferably, the wire piece **90** may have a shape illustrated in FIG. **25** as the present example. FIG. **25** is a schematic diagram illustrating the difference in the terminal between a comparative example and the present example (present embodiment). In the comparative example, the same or related elements as or to the elements of the present embodiment (the present example) are indicated by adding *r* to the end of the reference numerals in the present embodiment. In both the comparative example and the present example shown in FIG. **25**, the upper figure is a side view and the lower figure is a plan view in an A-plane view. The semiconductor device **10** of the present embodiment is, for example, similar to that in the first embodiment. The configuration illustrated in FIG. **25** is substantially the same on the upper arm **6H** side and the lower arm **6L** side.

[0190] The terminal is formed by punching a metal plate by press working. The wire piece is formed by capturing an image of the end face of the terminal with a camera, recognizing a corner portion of the end face, and ultrasonically bonding a bonding wire to a predetermined position with the corner portion as a position reference. A terminal **55r** of the comparative example has an R part **550r** formed by punching at a corner of one end face in the Z-direction. Therefore, at the time of forming a wire piece **90r** on the end face on the R part **550r** side, there is a possibility that the accuracy of the formation position of the wire piece **90r** becomes lower than that of the end face on the side where the R part **550r** is not provided.

[0191] In the present embodiment (present example) as well, similarly to the comparative example, the terminal **55** in the punched state has an R part (not illustrated) at a corner of one end face. However, after the punching, chamfering of the R part, for example, C-chamfering, is performed. The C-chamfering is chamfering with a chamfering angle of approximately 45 degrees. The terminal **55** has a chamfering part **550**.

Summary of Eighth Embodiment

[0192] As described above, the terminal **55** of the present embodiment has the chamfering part **550**. Thus, when the wire piece **90** on the end face on the side where the R part is formed at the time of punching, the corner portion can be accurately recognized by imaging. Therefore, the wire piece **90** can be formed with high positional accuracy.

[0193] The configuration of the present embodiment can be applied to a configuration including the terminal 55. Combinations with each of the preceding embodiments are possible. Further, the connection target of the wire piece 90 is not limited to the terminal 55. The present embodiment can be applied to a member formed by punching a metal plate and in which an R part is formed at the time of punching. By chamfering the R part after the punching, the wire piece 90 can be formed with high positional accuracy on the surface on the side where the R part is formed at the time of punching.

Ninth Embodiment

[0194] The present embodiment is a modification with the preceding embodiment as a basic form, and the description of the preceding embodiment can be incorporated. The present embodiment is characterized by the structure and the manufacturing method of the wire piece 90.

[0195] As described above, the wire piece 90 is formed by ultrasonically bonding the aluminum-based bonding wire and cutting the wire at the point when the first bonding is performed. One of preferable forms of the wire piece 90 is illustrated in FIGS. 26 to 29.

[0196] FIG. 26 illustrates a connection structure between the semiconductor element 30 and the heatsink 40 in the semiconductor device 10 according to the present embodiment. FIG. 27 is a sectional view taken along a line XXVII-XXVII of FIG. 26. FIG. 28 is a perspective view illustrating the wire piece 90 applied to FIGS. 26 and 27. FIG. 29 illustrates another example of the wire piece 90. In FIGS. 26 and 27, the number of wire pieces 90 is three. In FIGS. 26, 27, and 28, the illustration of the main electrode is omitted for convenience. The semiconductor device 10 of the present embodiment is, for example, similar to that in the first embodiment. The configurations illustrated in FIGS. 26 to 28 are substantially the same on the upper arm 6H side and the lower arm 6L side.

[0197] The semiconductor element 30 has a front surface 30a on which the emitter electrode 31 (not illustrated) is formed and a back surface 30b on which the collector electrode 32 (not illustrated) is formed. The collector electrode 32 forms the back surface 30b. As illustrated in FIGS. 21 and 22, a plurality of wire pieces 90 are arranged in the solder 80. The wire piece 90 is bonded (fixed) to the mounting surface 40a of the heatsink 40. The mounting surface 40a corresponds to the fixing surface of the wiring member. The wire piece 90 protrudes from the mounting surface 40a toward the back surface 30b. The wire piece 90 is held by the heatsink 40. For this reason, the heatsink 40 may be referred to as a holder. The wire piece 90 includes a fixed part 91, a flat part 92, and a non-fixed part 93. The fixed part 91 is a portion fixed (a portion bonded) to the heatsink 40 on the side of the wire piece 90 facing the heatsink 40.

[0198] The flat part 92 is a portion that is formed on the side of the wire piece 90 facing the back surface 30b of the semiconductor element 30 and is substantially parallel to the mounting surface 40a of the heatsink. The non-fixed part 93 is a portion that is continuous with the fixed part 91 on the side of the wire piece 90 facing the heatsink 40 and is not fixed to the heatsink 40. The non-fixed part 93 is separated from the mounting surface 40a in the Z-direction. The non-fixed part 93 floats with respect to the fixed part 91. The wire piece 90 is provided to be elastically deformable in the Z-direction. The solder 80 enters a gap between the non-fixed part 93 and the mounting surface 40a. The wire piece 90 has a fixed part 91 and a non-fixed part 93 on the heatsink 40 side in the Z-direction and has a flat part 92 on the side opposite to the fixed part 91 and the non-fixed part 93.

[0199] The wire piece 90 extends in the X-direction. The wire piece 90 illustrated in FIGS. 27 and 28 has the flat part 92 and the non-fixed part 93 at both ends in the extending direction. The flat part 92 is provided at a position overlapping with the non-fixed part 93 in a plan view. The height from the mounting surface 40a to the flat parts 92 at both ends are substantially equal to each other. The wire piece 90 has a substantially U shape or a substantially C shape on the ZX plane. The flat parts 92 at both ends are in contact with the back surface 30b of the semiconductor element 30.

[0200] FIG. 29 illustrates another example of the wire piece 90. The wire piece 90 has the flat part

92 not at both ends but only at one end in the extending direction. The non-fixed part **93** is provided at both ends in the extending direction. In the wire piece **90**, the heights from the mounting surface **40a** to the upper portions of both ends are different. The flat part **92** is formed at the end on the side where the protrusion from the mounting surface **40a** is higher. The wire piece **90** has a substantially J shape on the ZX plane. The flat part **92** is formed at the end on the side farther from the element center **30c** (not illustrated).

<Manufacturing Method>

[0201] Next, a method for manufacturing the semiconductor device **10**, particularly a method for manufacturing a connection body between the semiconductor element **30** and the heatsink **40**, will be described. Here, an example of the wire piece **90** illustrated in FIG. **29** is illustrated.

[0202] First, as illustrated in FIG. **30**, the wire piece **90** is formed on the mounting surface **40a** of the heatsink **40**. The bonding wire is bonded to the heatsink **40** by ultrasonic waves from a tool (not illustrated) to form the fixed part **91**. The fixed part **91** is a first bonding part. After the application of the ultrasonic wave is completed, the bonding wire is cut such that the non-fixed part **93** remains in front of and behind the fixed part **91** in the extending direction. In this manner, the bonding wire is cut without forming a second bonding part. Since the wire piece **90** is formed using only the first bond side, the formation time can be shortened as compared to a structure having two bonding bodies, that is, the first bonding part and the second bonding part. In addition, the size of the wire piece **90** can be reduced, for example, the extension length can be reduced. Hence it is also advantageous from the viewpoint of the solder deformation described above.

[0203] The bonding wire is a wire made of aluminum or an aluminum alloy as described above and can be selected in accordance with the size of the semiconductor element **30** or the thickness of the solder **80**. Here, the wire piece **90** having a protrusion height of 110 μm from the mounting surface **40a** and an extension length of 350 μm was formed using a bonding wire with a diameter of 80 μm .

[0204] Next, as illustrated in FIGS. **31** and **32**, the flat part **92** is formed in the wire piece **90**. That is, a leveling process is performed. Specifically, a load is applied to the wire piece **90** as indicated by a white arrow in FIG. **31** by using a jig **98** having a surface (hereinafter referred to as a contact surface) parallel to the mounting surface **40a**. For example, the jig **98** is attached to a press machine, and a load is applied to the wire piece **90**. The jig **98** is pressed against the wire piece **90** while the contact surface and the mounting surface **40a** are kept parallel to each other. The jig **98** is in contact with one end of the substantially J-shaped wire piece **90**. The wire piece **90** is elastically deformed, and at least a part of the non-fixed part **93** comes into contact with the mounting surface **40a**. When the jig **98** is further pressed, the wire piece **90** is plastically deformed to form the flat part **92**. The wire piece **90** is plastically deformed in accordance with the pressing amount. The flat part **92** is formed on one end side that first comes into contact with the jig **98**.

[0205] After the formation of the flat part **92**, the wire piece **90** is restored from the elastically deformed state by the release of the load, and the portion of the non-fixed part **93** in contact is separated from the mounting surface **40a**. Thus, as illustrated in FIG. **32**, the wire piece **90** including the flat part **92** at a position overlapping with the non-fixed part **93** in a plan view is obtained. By the flattening, the wire piece **90** becomes lower than in the state of FIG. **30**. Here, the height is about 75 μm . Through the above process, a plurality of wire pieces **90** are formed on the mounting surface **40a**. In order to prevent the inclination of the semiconductor element **30**, it is preferable to form a plurality of wire pieces, more preferably three or more wire pieces **90**. More preferably, the configuration described in the preceding embodiment may be adopted.

[0206] Next, as illustrated in FIG. **33**, molten solder **80S** is applied. The molten solder **80S** is applied onto the mounting surface **40a** of the heatsink **40**. The wire piece **90** is covered with the applied molten solder **80S**. Since it is necessary to dispose the semiconductor element **30** on the molten solder **80S**, the heatsink **40** is heated (heated) as necessary. Here, the molten solder **80S** was applied by a transfer method.

[0207] Next, as illustrated in FIG. **34**, the semiconductor element **30** is mounted. The

semiconductor element **30** is held by a jig (not illustrated) and lowered from above the mounting surface **40a** toward the molten solder **80S**. By lowering, the back surface **30b** of the semiconductor element **30** comes into contact with the molten solder **80S**, and presses and spreads the molten solder **80S**. When the jig is lowered to the predetermined position, the holding state by the jig is released. The molten solder **80S** wets and spreads on the back surface **30b** and the mounting surface **40a**. The semiconductor element **30** may be pressed against the wire piece **90** due to the thickness of the heatsink **40**, the thickness and warpage of the semiconductor element **30**, variations in mounting accuracy, and the like.

[0208] Then, the connection structure illustrated in FIG. **29** can be obtained through cooling (not illustrated). The wire piece **90** illustrated in FIGS. **27** and **28** can also be formed by a similar method. Specifically, after the fixed part **91** is formed, the bonding wire is cut such that the heights of both ends are substantially equal to form the wire piece **90**, and the flat parts **92** may be formed at both ends by the jig **98**.

Summary of Ninth Embodiment

[0209] When the wire piece **90** having no flat part, that is, the wire piece **90** in the state illustrated in FIG. **30**, is used, stress concentrates on the semiconductor element **30** when the semiconductor element **30** comes into contact with the wire piece **90**. In particular, when the height variation of the wire piece **90** is large, the possibility that the semiconductor element **30** comes into contact with the wire piece **90** increases. In contrast, by using the wire piece **90** of the present embodiment, the semiconductor element **30** comes into contact with the flat part **92**, so that stress concentration can be prevented. Further, the height variation of the wire piece **90** is reduced by forming the flat part **92**. As a result, the thickness of the solder **80** is stabilized, and connection reliability can be enhanced. For example, a solder crack life under a temperature cycle environment can be ensured. Since the wire piece **90** having the flat part **92** can be formed by a wire bonding technique and simple pressing, the cost can also be reduced.

[0210] The wire piece **90** includes the non-fixed part **93**. Thereby, the wire piece **90** can be deformed elastically. Thus, even when the semiconductor element **30** comes into contact with the wire piece **90**, the stress concentration of the semiconductor element **30** can be prevented due to the elastic change of the wire piece **90**. In particular, in the present embodiment, the flat part **92** is formed at a position overlapping with the non-fixed part **93** in a plan view. This facilitates the flat part **92** in contact with semiconductor element **30** to be deformed in the direction in which the stress is released. Therefore, it is more effective for preventing stress concentration.

[0211] The arrangement of the wire piece **90** is not limited to the above example. FIGS. **35** to **38** illustrate other examples. In each of the examples illustrated in FIGS. **35** to **38**, two wire pieces **90** are arranged in one cross section including the Z-direction. The wire piece **90** is in contact with the semiconductor element **30**.

[0212] In the example illustrated in FIGS. **35** to **37**, each of the two wire pieces **90** has only one flat part **92** similarly to the wire piece **90** illustrated in FIG. **29**. The flat part **92** is formed at each of the outer ends in the arrangement direction (X-direction) of the two wire pieces **90**. As illustrated in FIG. **35**, when the semiconductor element **30** is not warped, the flat parts **92** of both the wire pieces **90** come into contact with the semiconductor element **30**. Therefore, stress concentration in the semiconductor element can be prevented.

[0213] As illustrated in FIG. **36**, even when the semiconductor element **30** warps upward, the flat part **92** of the wire piece **90** comes into contact with the semiconductor element **30**. Therefore, stress concentration in the semiconductor element can be prevented. On the other hand, as illustrated in FIG. **37**, when the semiconductor element **30** warps downward, the inner end of the wire piece **90** comes into contact with the semiconductor element **30** as indicated by a solid arrow in the figure. As described above, depending on the warpage amount, the semiconductor element **30** may hit the end on the side where the flat part **92** is not formed.

[0214] The flat part **92** may be formed at the end of the wire piece **90**. According to this, even when

the warpage illustrated in FIG. 37 has occurred, the flat part 92 provided at the inner end comes into contact with the semiconductor element 30, so that stress concentration can be prevented. However, in a case where the semiconductor element 30 having an upward concave surface and the semiconductor element 30 having a downward concave surface are mixed in the same assembling lot, for example, when the position of the flat part 92 is aligned with the semiconductor element 30 having the upward convex surface, stress may concentrate on the semiconductor element 30 having the downward convex surface.

[0215] In contrast, in the example illustrated in FIG. 38, the two wire pieces 90 have flat parts 92 at both ends similarly to the wire pieces 90 illustrated in FIGS. 27 and 28. Therefore, when the semiconductor element 30 warps downward, the inner flat part 92 comes into contact with the semiconductor element 30. Although not illustrated, when the semiconductor element 30 warps upward, the outer flat part 92 comes into contact with the semiconductor element 30. Therefore, stress concentration can be prevented regardless of the direction of warpage of the semiconductor element 30.

[0216] The configuration of the wire piece 90 of the present embodiment is not limited to the wire piece 90 disposed in the solder 80. The configuration can be applied to any wire piece 90 provided in the solder bonding part between the main electrode and the wiring member. For example, in an example illustrated in FIG. 39, the wire piece 90 is disposed in the solder 81 between the emitter electrode 31 and the terminal 55 (not illustrated), and the flat part 92 is also formed in the wire piece 90. In FIG. 39, the flat part 92 is formed only at one end of the wire piece 90, but it goes without saying that the flat parts 92 may be formed at both ends.

[0217] The present embodiment can also be applied to a configuration in which the terminal 55 is not provided and a solder bonding part is formed between the heatsink 50 and the emitter electrode 31. In this case, the wire piece 90 bonded to the mounting surface 50a only needs to have the flat part 92. The present embodiment can also be applied to a configuration including only one of the front-side wiring member and the back-side wiring member.

[0218] The structure of the wire piece 90 described in the present embodiment can be combined with the wire piece 90 of the preceding embodiment. Further, the method for manufacturing the wire piece 90 described in the present embodiment can be applied to the formation of the wire piece 90 described in the preceding embodiment. Although the example in which the wire piece 90 includes the non-fixed part 93 has been described, the present disclosure is not limited thereto. At least the flat part 92 may be provided. The flat part 92 may be provided at a position not overlapping with the non-fixed part 93 in a plan view. The present embodiment can be applied to a wire piece disposed in a bonding part between the main electrode of the semiconductor element and the wiring member. The arrangement of the wire pieces is not limited to the arrangement described in the preceding embodiment.

Tenth Embodiment

[0219] The present embodiment is a modification with the preceding embodiment as a basic form, and the description of the preceding embodiment can be incorporated. In the present embodiment as well, a preferred embodiment of the wire piece 90 will be described.

<Magnitude of Wire Piece>

[0220] First, a preferable magnitude of the wire piece 90 will be described with reference to FIGS. 40 to 43. The wire piece 90 is disposed in a solder that connects the main electrode of the semiconductor element 30 and the wiring member. The solder here is, for example, the solder 80 and the solder 81.

[0221] FIG. 40 is a simulation result illustrating the relationship between the volume of the wire piece 90 and the solder deformation. The horizontal axis represents the volume ($\times 10^{10} \mu\text{m}^3$) of the wire piece 90, and the vertical axis represents the solder deformation (arbitrary unit). The horizontal axis is a logarithmic axis. FIG. 41 is a diagram illustrating the wire piece 90 of the present embodiment. In FIG. 41, the upper part of the page is a side view, and the lower part

of the page is a top plan view. FIG. 42 is a sectional view for explaining the maximum height of the wire piece 90 disposed in the solder 80. FIG. 43 is a sectional view for explaining the maximum height of the wire pieces 90 arranged in the solder 81.

[0222] From the simulation result illustrated in FIG. 40, it has become clear that when the volume of the wire piece 90 is large, thermal stress based on the difference in a linear expansion coefficient between the wire piece 90 and the solder, that is, solder deformation, increases, and when the volume exceeds a predetermined volume, element damage such as a crack occurs. When the solder deformation becomes a value equal to or more than a broken line illustrated in FIG. 40, the element damage occurs. Thus, for preventing the element damage, it is preferable to set the volume of the wire piece 90 to $1.0 \times 10^{10} \mu\text{m}^3$ or less. In the semiconductor device 10 of the present embodiment, the volume of each wire piece 90 is set to $1.0 \times 10^{10} \mu\text{m}^3$ or less.

[0223] Next, a description will be given of a configuration in which the height variation of the wire piece 90 can be prevented without performing the leveling process while the volume relationship described above is satisfied. Hereinafter, the wire piece 90 connected to the heatsink 40 will be exemplified.

[0224] As illustrated in FIG. 41, the wire piece 90 is divided into three portions in the extending direction. The wire piece 90 includes a bonding part 94, a feed part 95, and a tail part 96. The bonding part 94 is located between the feed part 95 and the tail part 96 in the extending direction of the wire piece 90. The bonding part 94 is a portion bonded to the heatsink 40. The bonding part 94 has a fixed part 91 on the side facing the heatsink 40. The bonding part 94 includes the fixed part 91 and is a portion overlapping with the fixed part 91 in a plan view. That is, the bonding part 94 is a portion immediately above the fixed part 91 and the fixed part 91. The bonding part 94 corresponds to a bonding part. The bonding part 94 is crushed by receiving a load from the tool at the time of ultrasonic bonding. Hence the bonding part 94 is wider than the feed part 95 and the tail part 96.

[0225] The feed part 95 is continuous with the bonding part 94 on the tip side of the wire piece 90. The feed part 95 is a portion that is not bonded to the heatsink 40. The feed part 95 has a non-fixed part 93 on the side facing the heatsink 40. The feed part 95 is a portion including the non-fixed part 93 on the tip side and overlapping with the non-fixed part 93 in a plan view. That is, the feed part 95 is the non-fixed part 93 on the tip side and a portion immediately above the non-fixed part 93. The feed part 95 does not have the flat part 92 on the side facing the semiconductor element 30 (not illustrated).

[0226] The tail part 96 is continuous with the bonding part 94 on the rear end side of the wire piece 90. Similar to the feed part 95, the tail part 96 is also a portion not bonded to the heatsink 40. The tail part 96 has the non-fixed part 93 on the side facing the heatsink 40. The tail part 96 is a portion including the non-fixed part 93 on the rear end side and overlapping with the non-fixed part 93 in a plan view. That is, the tail part 96 is the non-fixed part 93 on the rear end side and a portion immediately above the non-fixed part 93. The tail part 96 does not have a flat part 92 on the side facing the semiconductor element 30 (not illustrated).

[0227] The feed part 95 and the tail part 96 correspond to a non-bonding part. The tip side is the side having the end (cut end) before the ultrasonic bonding. The rear end side is the end side formed by cutting the bonding wire after the ultrasonic bonding. Although not illustrated, the heatsink 40 has a cutter mark generated when the bonding wire is cut immediately below the rear end of the wire piece 90.

[0228] Hereinafter, the length of the bonding part 94 in the extending direction may be referred to as LB, the length of the feed part 95 in the extending direction may be referred to as LF, and the length of the tail part 96 in the extending direction may be referred to as LT. The length (total length) of the wire piece 90 in the extending direction may be referred to as LW, and the width of the bonding part 94 may be referred to as WB. The width WB is the length of the bonding part 94 in a direction orthogonal to the extending direction. The height of the bonding part 94 may be

denoted by HB, the height of the feed part **95** may be denoted by HF, and the height of the tail part **96** may be denoted by HT. As illustrated in FIG. **41**, the length LF of the feed part **95** and the length LT of the tail part **96** are not the lengths on the side (lower surface side) facing the heatsink **40** but the lengths on the side (upper surface side) facing the semiconductor element **30**. The height is a height of a portion farthest in the Z-direction from the first facing surface that is the bonding surface.

[0229] When the wire piece **90** is formed using a bonding wire having a diameter of 80 μm , the length LB of the bonding part **94** is substantially the same in the configuration including the flat part **92** and the present embodiment. For example, the length LB is $260\ \mu\text{m} \pm 100\ \mu\text{m}$. In order to set the volume of the wire piece **90** to $1.0 \times 10^7\ \mu\text{m}^3$ or less, the total length LW of the wire piece **90** is preferably set to 400 μm or more and 450 μm or less, and the lengths LF, LT of the feed part **95** and the tail part **96** are preferably set to 100 μm or less.

[0230] In the configuration in which the flat part **92** is provided, a length for ensuring the flat part **92** in the extending direction is required. When the flat parts **92** are provided on both end sides, the total length of the wire piece **90** exceeds 450 μm , for example, about 500 μm . In the present embodiment, since the flat part **92** is not provided, each of the lengths LF, LT of the feed part **95** and the tail part **96**, which are non-bonding parts, can be reduced to 100 μm or less. Therefore, even when the length LB varies, the total length LW of the wire piece **90** can be set to 450 μm or less. That is, the wire piece **90** can be reduced in size. It is thus easy to set the volume of the wire piece **90** to $1.0 \times 10^7\ \mu\text{m}^3$ or less. In addition, with the lengths LF, LT being small, variations in the heights HF, HT can be prevented.

[0231] Furthermore, the height HF of the feed part **95** and the height HT of the tail part **96** may be set to 80 μm or more and 100 μm or less. The height of 80 μm is equal to the wire diameter. In this case, the feed part **95** and the tail part **96** are in contact with, but not bonded to, the mounting surface **40a** of the heatsink **40**.

[0232] When the semiconductor element **30** can be warped downward, as illustrated in FIG. **42**, the volume of the space in which the semiconductor element **30** without warpage and the heatsink **40** face each other is maximum. When the volume of the facing space is maximum, the largest amount of solder is required as the solder **80** for ensuring a bonding area where the solder wets and spreads on almost the entire surface of the collector electrode **32**. The volume of the necessary solder is minimized in a state where the semiconductor element **30** is supported by the wire pieces **90**. The minimum value of the required solder volume is a value obtained by excluding the sink of the solder **80** from the volume of the portion overlapping with the semiconductor element **30** (collector electrode **32**) in a plan view when the thickness of the solder **80** is equal to the heights HF, HT.

[0233] When the heights HF, HT are set to 110 μm or more, the predetermined supply amount of the solder **80** may fall below the minimum value of the required solder volume. This is apparent from the simulation results. In this case, there is a possibility that the solder **80** wets and spreads only on a part of the collector electrode **32**. When the solder heights HF, HT are set to 100 μm or less, the predetermined supply amount of the solder **80** exceeds the minimum value of the required solder volume. As a result, the solder **80** wets and spreads over almost the entire surface of the collector electrode **32**, and connection reliability can be ensured.

[0234] The same applies to the solder **81** on the emitter electrode **31** side. In a case where the semiconductor element **30** can warp downward, as illustrated in FIG. **43**, when the warpage is maximum (e.g., 0.1 μm), the volume of the space in which the semiconductor element **30** and the terminal **55** face each other is maximum. When the volume of the facing space is maximum, the largest amount of solder is required as the solder **81** for ensuring a bonding area where the solder wets and spreads on almost the entire surface of the emitter electrode **31**. The volume of the necessary solder is minimized in a state where the semiconductor element **30** is supported by the wire pieces **90**.

[0235] When the heights HF, HT are set to 110 μm or more, the predetermined supply amount of

the solder **80** may fall below the minimum value of the required solder volume. This is apparent from the simulation results. In this case, there is a possibility that the solder **81** wets and spreads only on a part of the emitter electrode **31**. When the solder heights HF, HT are set to 100 μm or less, the predetermined supply amount of the solder **81** exceeds the minimum value of the required solder volume. As a result, almost the entire surface of the emitter electrode **31** wets and spreads through the solder **81**, and connection reliability can be ensured.

[0236] As illustrated in the preceding embodiment (cf. FIG. **14**), even in a case where the semiconductor element **30** having the downward convex surface is disposed in an inclined manner, when the heights HF, HT are 70 μm or more, the minimum film thicknesses of the solder **80** and the solder **81** can be ensured by the wire pieces **90** (cf. FIGS. **12** and **20**) arranged at least at the four corners. The minimum film thickness with which connection reliability can be ensured is, for example, 43 μm . In the present embodiment, the wire diameter is 80 μm , and the minimum value of each of the heights HF, HT is 80 μm . Therefore, even when the semiconductor element **30** having the downward convex surface is disposed in an inclined manner, connection reliability can be ensured.

[0237] When the lengths LF, LT are reduced as described above, the ratio (LF/LB, LT/LB) of each of the lengths LF, LT of the feed part **95** or the tail part **96** to the length LB of the bonding part **94** is smaller than that in the configuration in which the flat part **92** is provided. In order to set the volume of the wire piece **90** to $1.0 \times 10^7 \mu\text{m}^3$ or less, it is preferable to set LF/LB and LT/LB to 0.1 or more and 0.65 or less. By satisfying this relationship, the lengths of the feed part **95** and the tail part **96** can be reduced with respect to the bonding part **94**, and the wire piece **90** can be reduced in size. Further, it is possible to prevent variations in the heights HF, HT.

[0238] A ratio (WB/LB) of the width WB of the bonding part **94** to the length LB of the bonding part **94** may be set to 0.2 or more and 0.7 or less. That is, the width WB may be narrowed. Thus, the volume of the wire piece **90** can be reduced. Further, it is possible to prevent variations in the heights HF, HT.

[0239] More specifically, the wire piece **90** may be formed to achieve the following dimensions. The total length LW of the wire piece **90** may be $420 \mu\text{m} \pm 20 \mu\text{m}$, the length LF of the feed part **95** may be $85 \mu\text{m} \pm 15 \mu\text{m}$, and the length LT of the tail part **96** may be $70 \pm 30 \mu\text{m}$. The length LB of the bonding part **94** may be $260 \mu\text{m} \pm 100 \mu\text{m}$, the height HB of the bond part may be $70 \mu\text{m} \pm 5 \mu\text{m}$, and the width WB of the bonding part **94** may be $90 \mu\text{m} \pm 15 \mu\text{m} - 5 \mu\text{m}$. The height HF of the feed part **95** may be $85 \mu\text{m} \pm 15 \mu\text{m} - 5 \mu\text{m}$, and the height HT of the tail part **96** may be $85 \mu\text{m} \pm 5 \mu\text{m}$.

<Method for Manufacturing Wire Piece>

[0240] Next, a method for manufacturing the wire piece **90** that achieves the volume and dimension described above will be described with reference to FIGS. **44** to **48**. Hereinafter, an example in which the wire piece **90** is provided on the heatsink **40** will be described, but the same applies to the terminal **55**.

[0241] As illustrated in FIG. **44**, an ultrasonic bonding apparatus includes a wire guide **100**, a tool **101**, and a cutter **102**. First, a bonding wire **99** pulled out from the wire guide **100** is disposed at a predetermined position on the mounting surface **40a** of the heatsink **40**. At this time, the bonding wire **99** is disposed such that the feed part **95** having the predetermined length described above can be ensured with reference to the place of bonding by the tool **101**.

[0242] Next, as illustrated in FIG. **45**, ultrasonic bonding is performed by the tool **101**. The bonding part **94** is formed by ultrasonic bonding. The bonding wire **99** is more or less crushed by the power of ultrasonic bonding and the load by the tool **101**. This leads to an increase in the width of the bonding part **94**. In the present embodiment, the power and the load are adjusted such that the width WB of the bonding part **94** is not excessively widened and falls within the range of $90 \mu\text{m} + 15 \mu\text{m} - 5 \mu\text{m}$, that is, 85 μm to 105 μm .

[0243] By ultrasonic bonding, compressive stress acts on the upper surface side of the feed part **95** as indicated by an arrow in FIG. **45**. On the other hand, tensile stress acts on the lower surface side

of the feed part **95**, that is, the heatsink **40** side. Thus, the feed part **95** bounces against the mounting surface **40a** of the heatsink **40**. The portion of the non-fixed part **93** in contact is separated from the mounting surface **40a**.

[0244] After the ultrasonic bonding is completed, the tool **101** (ultrasonic bonding apparatus) is retracted as illustrated in FIG. **46**. The retraction amount of the tool **101** indicated by a white arrow in FIG. **46** is determined in accordance with the cutting position of the cutter **102**, that is, the length of the tail part **96**. Specifically, the retraction amount is determined such that the length LT of the tail part **96** and the entire length of the wire piece **90** each have a predetermined length.

[0245] Next, as illustrated in FIG. **47**, wire cutting is performed. The bonding wire **99** is cut by the cutter **102** in a state where the tool **101** presses the bonding wire **99** at the retracted position described above. The wire piece **90** is formed by wire cutting. After the wire cutting, the ultrasonic bonding apparatus including the tool **101** is retracted as illustrated in FIG. **48**. The load is released by the cutting, and the tail part **96** of the wire piece **90** is restored from the elastically deformed state and bounces against the mounting surface **40a** of the heatsink **40**. The portion of the non-fixed part **93** in contact is separated from the mounting surface **40a**.

[0246] As illustrated in FIG. **48**, a cutter mark **41** is formed on the heatsink **40** by wire cutting. The cutter mark **41** is formed immediately below the tail part **96** at one of both ends of the wire piece **90** in the extending direction.

Summary of Tenth Embodiment

[0247] In the present embodiment, the volume of the wire piece **90** is set to $1.0 \times 10^7 \mu\text{m}^3$ or less. As a result, it is possible to reduce thermal stress and thus prevent the element damage. That is, it is possible to improve the reliability of the semiconductor device **10**.

[0248] In the preceding embodiment (cf. FIG. **28**), the volume relationship described above may be satisfied. However, when the flat parts **92** are provided on both end sides, the total length LW of the wire piece **90** becomes large. In addition, when the leveling process is not performed, a variation in the wire height, that is, the heights HF, HT, is large. As the leveling process is required, the number of steps, and thus the number of manufacturing steps, increases.

[0249] In the present embodiment, in order to satisfy the volume relationship described above, the total length LW of the wire piece **90** is set to 400 μm or more and 450 μm or less, and the lengths LF, LT of the feed part **95** and the tail part **96** are set to 100 μm or less. Since the flat part **92** is not provided, the lengths LF, LT of the feed part **95** and the tail part **96** and the total length LW of the wire piece **90** can be reduced. In addition, the leveling process is unnecessary, and for example, manufacturing cost can be reduced.

[0250] In particular, the lengths LF, LT of the feed part **95** and the tail part **96** are reduced with respect to the length LB of the bonding part **94**. Specifically, LF/LB and LT/LB are set to 0.1 or more and 0.65 or less. This makes it possible to prevent variations in the heights HF, HT.

[0251] In the present embodiment, the height HF of the feed part **95** and the height HT of the tail part **96** are set to 80 μm or more and 100 μm or less. This makes it possible to ensure connection reliability.

[0252] In the present embodiment, the ratio (WB/LB) of the width WB of the bonding part **94** to the length LB of the bonding part **94** is set to 0.2 or more and 0.7 or less. Since the width WB is narrowed, the volume of the wire piece **90** can be reduced. In addition, in order to narrow the width WB, power and load at the time of ultrasonic bonding are held within ranges in which bonding strength can be ensured. As a result, it is possible to reduce the amount of crushing and thus prevent variations in the heights HF, HT.

[0253] The wire piece **90** having no flat part **92** illustrated in the present embodiment can be combined with each of the first to eighth embodiments. For example, it is suitable for a configuration in which the wire pieces **90** are arranged only at the four corners illustrated in FIGS. **12** and **20**. The present embodiment can be applied to a wire piece disposed in a bonding part between the main electrode of the semiconductor element and the wiring member. The arrangement

of the wire pieces is not limited to the arrangement described in the preceding embodiment.

Other Embodiments

[0254] Although the example in which the semiconductor device **10** is applied to the inverter **5** has been described, the present disclosure is not limited thereto. For example, the present disclosure can also be applied to a converter. The present disclosure can also be applied to both the inverter **5** and the converter.

[0255] Although the example in which the semiconductor element **30** includes the IGBT **6i** and the FWD **6d** constituting one arm has been described, the present disclosure is not limited thereto. The IGBT **6i** and the FWD **6d** may be separate chips (separate elements). Although the example of the IGBT **6i** has been shown as the switching element, the present disclosure is not limited thereto. For example, a MOSFET can also be adopted. In addition, a diode can also be adopted as an element with a vertical structure having main electrodes on both surfaces.

[0256] A plurality of semiconductor elements **30H** may be provided, and the plurality of semiconductor elements **30H** may be connected in parallel to form one of the upper arms **6H**. A plurality of semiconductor elements **30L** may be provided, and the plurality of semiconductor elements **30L** may be connected in parallel to form one of the lower arms **6L**.

[0257] Although the example in which the back surfaces **40b**, **50b** of the heatsinks **40**, **50** are exposed from the sealing resin body **20** has been described, the present disclosure is not limited thereto. At least one of the back surfaces **40b**, **50b** may be covered with the sealing resin body **20**. At least one of the back surfaces **40b**, **50b** may be covered with an insulating member (not illustrated) different from the sealing resin body **20**. Although the example in which the semiconductor device **10** includes the sealing resin body **20** has been described, the present disclosure is not limited thereto. The sealing resin body **20** may not be provided.

[0258] The example in which the semiconductor device **10** includes the plurality of semiconductor elements **30** constituting the upper and lower arm circuit **6** for one phase has been described, but the present disclosure is not limited thereto. Only the semiconductor element constituting one arm may be provided. It is sufficient that the semiconductor device **10** include, for example, a semiconductor element **30** constituting one arm and a pair of heatsinks **40**, **50** disposed to sandwich the semiconductor element **30**. Further, the semiconductor elements constituting the upper and lower arm circuit **6** for three phases may be provided as one package.

[0259] Although the example in which the signal terminal **75** is connected to the pad **33** via the bonding wire **87** has been described, the present disclosure is not limited thereto. For example, the signal terminal **75** may be connected to the pad **33** via solder. Since a space for the bonding wire **87** is unnecessary, a configuration without the terminal **55** can be adopted.

[0260] Although the example in which the groove **51** is provided in the heatsink **50** and the groove **63** is provided in the couplings **61**, **62** has been described, the present disclosure is not limited thereto. At least one of the grooves **51**, **63** may be eliminated. The example in which the coupling portion coupling between the upper arm **6H** and the lower arm **6L** is realized by the connection structure of the two couplings **60**, **61** has been described, but the present disclosure is not limited thereto. A coupling continuous with one of the heatsinks **40L**, **50H** may be connected to the other. The example in which the coupling **62** is provided has been described, but the present disclosure is not limited thereto. The main terminal **71** may be continuous with the heatsink **50L** without interposing the coupling **62**.

[0261] While the present disclosure has been described in accordance with the above embodiments, it is understood that the present disclosure is not limited to the above embodiments and structures. The present disclosure embraces various changes and modifications within the range of equivalency. In addition, various combinations and modifications and other combinations and modifications including only one element or more or less than one element are within the scope and spirit of the present disclosure.

Claims

1. A semiconductor device comprising: a semiconductor element having a front surface and a back surface opposite to the front surface in a plate thickness direction of the semiconductor element, the semiconductor element including, as main electrodes, a front electrode on the front surface and a back electrode on the back surface, the back electrode having an area larger than an area of the front electrode; a bonding member disposed between a first facing surface and a second facing surface to form a bonding part; a wiring member electrically connected to at least one of the main electrodes through the bonding member; and a plurality of wire pieces disposed in the bonding member, and fixed to the first facing surface to protrude from the first facing surface, wherein the wiring member includes a back-side wiring member disposed adjacent to the back surface of the semiconductor element and electrically connected to the back electrode, the bonding member includes a back-side bonding member that forms a bonding part between the back electrode and the back-side wiring member, the back-side bonding member has, in a plan view in the plate thickness direction, a central region that overlaps with a central portion of the semiconductor element including an element center, and an outer peripheral region that includes a portion overlapping with an outer peripheral portion of the semiconductor element surrounding the central portion and surrounds the central region, the plurality of wire pieces include at least four wire pieces disposed in the outer peripheral region of the back-side bonding member at positions corresponding to at least four respective corners of the semiconductor element, the plurality of wire pieces include at least one wire piece disposed to extend toward the element center in the plan view, the plurality of wire pieces are fixed to a surface of the wiring member in a bonding part between the at least one of the main electrodes and the wiring member, each of the plurality of wire pieces has a volume of $1.0 \times 10^{10} \mu\text{m}^3$ or less, and each of the plurality of wire pieces includes a bonding part bonded to the surface of the wiring member, and non-bonding parts extending from opposite ends of the bonding part in an extending direction of the wire piece without being bonded to the wiring member.
2. The semiconductor device according to claim 1, wherein in the extending direction, a length of the wire piece is $400 \mu\text{m}$ or more and $450 \mu\text{m}$ or less, and a length of each of the non-bonding parts is $100 \mu\text{m}$ or less.
3. The semiconductor device according to claim 2, wherein a height of each of the non-bonding parts from the surface of the wiring member to which the bonding part is bonded is $80 \mu\text{m}$ or more and $100 \mu\text{m}$ or less.
4. The semiconductor device according to claim 1, wherein a ratio of a length of each of the non-bonding parts to a length of the bonding part in the extending direction is 0.1 or more and 0.65 or less.
5. The semiconductor device according to claim 1, wherein a ratio of a width of the bonding part to a length of the bonding part in the extending direction is 0.2 or more and 0.7 or less.
6. A semiconductor device comprising: a semiconductor element having a front surface and a back surface opposite to the front surface in a plate thickness direction of the semiconductor element, the semiconductor element including, as main electrodes, a front electrode on the front surface and a back electrode on the back surface, the back electrode having an area larger than an area of the front electrode; a bonding member disposed between a first facing surface and a second facing surface to form a bonding part; a wiring member electrically connected to at least one of the main electrodes through the bonding member; and a plurality of wire pieces disposed in the bonding member, and fixed to the first facing surface to protrude from the first facing surface, wherein the wiring member includes a back-side wiring member disposed adjacent to the back surface of the semiconductor element and electrically connected to the back electrode, the bonding member includes a back-side bonding member that forms a bonding part between the back electrode and the

back-side wiring member, the back-side bonding member has, in a plan view in the plate thickness direction, a central region that overlaps with a central portion of the semiconductor element including an element center, and an outer peripheral region that includes a portion overlapping with an outer peripheral portion of the semiconductor element surrounding the central portion and surrounds the central region, the plurality of wire pieces include at least four wire pieces disposed in the outer peripheral region of the back-side bonding member at positions corresponding to at least four respective corners of the semiconductor element, the plurality of wire pieces include at least one wire piece disposed to extend toward the element center in the plan view, and the plurality of wire pieces include at least three wire pieces disposed in the central region of the back-side bonding member to surround the element center.

7. The semiconductor device according to claim 6, wherein the wiring member includes a front-side wiring member disposed adjacent to the front surface of the semiconductor element and electrically connected to the front electrode, the bonding member includes a front-side bonding member that forms a bonding part between the front electrode and the front-side wiring member, and the plurality of wire pieces include a plurality of front-side wire pieces disposed in the front-side bonding member.

8. The semiconductor device according to claim 7, wherein the semiconductor element includes: a gate pad disposed on the front surface; a gate wiring disposed adjacent to the front surface and continuous with the gate pad; and a gate wiring protection part disposed on the front surface as a part of a protective film protecting the gate wiring, and in the front-side bonding member, the plurality of front-side wire pieces are disposed at positions without overlapping with the gate wiring protection part.

9. A semiconductor device comprising: a semiconductor element having a front surface and a back surface opposite to the front surface in a plate thickness direction of the semiconductor element, the semiconductor element including, as main electrodes, a front electrode on the front surface and a back electrode on the back surface, the back electrode having an area larger than an area of the front electrode; a bonding member disposed between a first facing surface and a second facing surface to form a bonding part; a wiring member electrically connected to at least one of the main electrodes through the bonding member; and a plurality of wire pieces disposed in the bonding member, and fixed to the first facing surface to protrude from the first facing surface, wherein the wiring member includes a back-side wiring member disposed adjacent to the back surface of the semiconductor element and electrically connected to the back electrode, the bonding member includes a back-side bonding member that forms a bonding part between the back electrode and the back-side wiring member, the back-side bonding member has, in a plan view in the plate thickness direction, a central region that overlaps with a central portion of the semiconductor element including an element center, and an outer peripheral region that includes a portion overlapping with an outer peripheral portion of the semiconductor element surrounding the central portion and surrounds the central region, the plurality of wire pieces include at least four back-side wire pieces disposed in the outer peripheral region of the back-side bonding member at positions corresponding to at least four respective corners of the semiconductor element, the plurality of wire pieces include at least one back-side wire piece disposed in the back-side bonding member to extend toward the element center in the plan view, the wiring member includes a front-side wiring member disposed adjacent to the front surface of the semiconductor element and electrically connected to the front electrode, the bonding member includes a front-side bonding member that forms a bonding part between the front electrode and the front-side wiring member, the plurality of wire pieces include a plurality of front-side wire pieces disposed in the front-side bonding member, the semiconductor element includes: a gate pad disposed on the front surface; a gate wiring disposed adjacent to the front surface and continuous with the gate pad; and a gate wiring protection part disposed on the front surface as a part of a protective film protecting the gate wiring, and in the front-side bonding member, the plurality of front-side wire pieces are disposed at positions without overlapping with

the gate wiring protection part.

10. The semiconductor device according to claim 9, wherein the front-side wire pieces in the front-side bonding member are disposed at positions without overlapping the back-side wire pieces in the back-side bonding member.

11. A semiconductor device comprising: a semiconductor element having a front surface and a back surface opposite to the front surface in a plate thickness direction of the semiconductor element, the semiconductor element including, as main electrodes, a front electrode on the front surface and a back electrode on the back surface, the back electrode having an area larger than an area of the front electrode; a bonding member disposed between a first facing surface and a second facing surface to form a bonding part; a wiring member electrically connected to at least one of the main electrodes through the bonding member; and a plurality of wire pieces disposed in the bonding member, and fixed to the first facing surface to protrude from the first facing surface, wherein the wiring member includes a back-side wiring member disposed adjacent to the back surface of the semiconductor element and electrically connected to the back electrode, the bonding member includes a back-side bonding member that forms a bonding part between the back electrode and the back-side wiring member, the back-side bonding member has, in a plan view in the plate thickness direction, a central region that overlaps with a central portion of the semiconductor element including an element center, and an outer peripheral region that includes a portion overlapping with an outer peripheral portion of the semiconductor element surrounding the central portion and surrounds the central region, the plurality of wire pieces include at least four back-side wire pieces disposed in the outer peripheral region of the back-side bonding member at positions corresponding to at least four respective corners of the semiconductor element, the plurality of wire pieces include at least one back-side wire piece disposed in the back-side bonding member to extend toward the element center in the plan view, the wiring member includes a front-side wiring member disposed adjacent to the front surface of the semiconductor element and electrically connected to the front electrode, the bonding member includes a front-side bonding member that forms a bonding part between the front electrode and the front-side wiring member, the plurality of wire pieces include a plurality of front-side wire pieces disposed in the front-side bonding member, and the front-side wire pieces are disposed in the front-side bonding member at positions without overlapping with the back-side wire pieces in the back-side bonding member.

12. The semiconductor device according to claim 11, wherein the front-side wiring member includes a first wiring member and a second wiring member that is connected to the front electrode via the first wiring member, the front-side bonding member includes a first bonding member disposed adjacent to the front surface, and a second bonding member that forms a bonding part between the second wiring member and the first wiring member, the front-side wire pieces include first front-side wire pieces disposed in the first bonding member, and second front-side wire pieces disposed in the second bonding member, a number of the back-side wire pieces, a number of the first front-side wire pieces and a number of the second front-side wire pieces are different from each other, and the number of the back-side wire pieces is the largest and the number of the second front-side wire pieces is the smallest.

13. A semiconductor device comprising: a semiconductor element having a front surface and a back surface opposite to the front surface in a plate thickness direction of the semiconductor element, the semiconductor element including, as main electrodes, a front electrode on the front surface and a back electrode on the back surface, the back electrode having an area larger than an area of the front electrode; a bonding member disposed between a first facing surface and a second facing surface to form a bonding part; a wiring member electrically connected to at least one of the main electrodes through the bonding member; and a plurality of wire pieces disposed in the bonding member, and fixed to the first facing surface to protrude from the first facing surface, wherein the wiring member includes a back-side wiring member disposed adjacent to the back surface of the semiconductor element and electrically connected to the back electrode, the bonding member

includes a back-side bonding member that forms a bonding part between the back electrode and the back-side wiring member, the back-side bonding member has, in a plan view in the plate thickness direction, a central region that overlaps with a central portion of the semiconductor element including an element center, and an outer peripheral region that includes a portion overlapping with an outer peripheral portion of the semiconductor element surrounding the central portion and surrounds the central region, the plurality of wire pieces include at least four back-side wire pieces disposed in the outer peripheral region of the back-side bonding member at positions corresponding to at least four respective corners of the semiconductor element, the plurality of wire pieces include at least one back-side wire piece disposed in the back-side bonding member to extend toward the element center in the plan view, the wiring member includes a front-side wiring member disposed adjacent to the front surface of the semiconductor element and electrically connected to the front electrode, the bonding member includes a front-side bonding member that forms a bonding part between the front electrode and the front-side wiring member, the front-side wiring member includes a first wiring member and a second wiring member that is connected to the front electrode via the first wiring member, the front-side bonding member includes a first bonding member disposed adjacent to the front surface, and a second bonding member that forms a bonding part between the second wiring member and the first wiring member, the front-side wire pieces include first front-side wire pieces disposed in the first bonding member, and second front-side wire pieces disposed in the second bonding member, a number of the back-side wire pieces, a number of the first front-side wire pieces and a number of the second front-side wire pieces are different from each other, and the number of the back-side wire pieces is the largest and the number of the second front-side wire pieces is the smallest.

14. The semiconductor device according to claim 13, wherein a height of each of the wire pieces fixed to the first facing surface is less than a thickness of the bonding member that forms the bonding part between the first facing surface and the second facing surface.
